

(12) **United States Patent**  
**Pendse**

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(54) **SEMICONDUCTOR DEVICE AND METHOD OF SELF-CONFINEMENT OF CONDUCTIVE BUMP MATERIAL DURING REFLOW WITHOUT SOLDER MASK**

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See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

5,186,383 A 2/1993 Melton et al.

5,340,435 A 8/1994 Ito et al.

(Continued)

FOREIGN PATENT DOCUMENTS

JP 04-355933 9/1992

JP 2005-28037 4/1993

(Continued)

OTHER PUBLICATIONS

Chen et al., “Advanced Flip-Chip Package Production Solution for 40nm/28nm Technology Nodes”, International Electron Devices Meeting, pp. 768-771, IEEE 2010.

(Continued)

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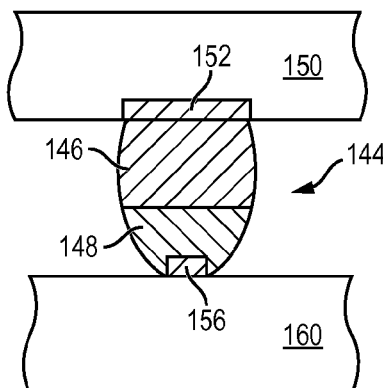
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**ABSTRACT**

A semiconductor device has a semiconductor die with a die bump pad. A substrate has a conductive trace with an interconnect site. A conductive bump material is deposited on the interconnect site or die bump pad. The semiconductor die is mounted over the substrate so that the bump material is disposed between the die bump pad and interconnect site. The bump material is reflowed without a solder mask around the die bump pad or interconnect site to form an interconnect structure between the die and substrate. The bump material is self-confined within the die bump pad or interconnect site. The volume of bump material is selected so that a surface tension maintains self-confinement of the bump material substantially within a footprint of the die bump pad and interconnect site. The interconnect structure can have a fusible portion and non-fusible portion. An encapsulant is deposited between the die and substrate.

**17 Claims, 22 Drawing Sheets**



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(56)

**References Cited****U.S. PATENT DOCUMENTS**

5,378,859 A 1/1995 Shirasaki et al.  
 5,383,916 A 1/1995 Brown  
 5,386,624 A 2/1995 George et al.  
 5,434,410 A 7/1995 Kulwicki  
 5,508,561 A 4/1996 Tago et al.  
 5,519,580 A 5/1996 Natarajan et al.  
 5,587,337 A 12/1996 Idaka et al.  
 5,650,595 A 7/1997 Bentlage et al.  
 5,697,148 A 12/1997 Lance, Jr. et al.  
 5,710,071 A 1/1998 Beddingfield et al.  
 5,795,818 A 8/1998 Marrs  
 5,796,591 A 8/1998 Dalal et al.  
 5,798,285 A 8/1998 Bentlage et al.  
 5,844,782 A 12/1998 Fukasawa  
 5,854,514 A 12/1998 Roldan et al.  
 5,869,886 A 2/1999 Tokuno  
 5,872,399 A 2/1999 Lee  
 5,889,326 A 3/1999 Tanaka  
 5,894,173 A 4/1999 Jacobs et al.  
 5,915,169 A 6/1999 Heo  
 5,985,456 A 11/1999 Zhou et al.  
 6,002,172 A 12/1999 Desai et al.  
 6,049,122 A 4/2000 Yoneda  
 6,109,507 A 8/2000 Yagi et al.  
 6,149,122 A 11/2000 Berger et al.  
 6,201,305 B1 3/2001 Darveaux et al.  
 6,218,630 B1 4/2001 Takigami  
 6,228,466 B1 5/2001 Tsukada et al.  
 6,229,209 B1 5/2001 Nakamura et al.  
 6,229,220 B1 5/2001 Saitoh et al.  
 6,229,711 B1 5/2001 Yoneda  
 6,251,704 B1 6/2001 Ohuchi et al.  
 6,259,159 B1 7/2001 Dalal et al.  
 6,259,163 B1 7/2001 Ohuchi et al.  
 6,281,107 B1 8/2001 Moriyama  
 6,281,450 B1 8/2001 Urasaki et al.  
 6,281,581 B1 8/2001 Desai et al.  
 6,297,560 B1 10/2001 Capote et al.  
 6,297,564 B1 10/2001 Chung  
 6,324,754 B1 12/2001 DiStefano et al.  
 6,326,241 B1 12/2001 Belke, Jr. et al.  
 6,329,605 B1 12/2001 Beroz et al.

(56)

## References Cited

## U.S. PATENT DOCUMENTS

6,333,206	B1	12/2001	Ito et al.	7,317,245	B1	1/2008	Lee et al.
6,335,222	B1	1/2002	DiStefano	7,361,990	B2	4/2008	Lu et al.
6,335,568	B1	1/2002	Yuzawa et al.	7,405,484	B2	7/2008	Usui et al.
6,335,571	B1	1/2002	Capote et al.	7,436,063	B2	10/2008	Miyata et al.
6,383,916	B1	5/2002	Lin	7,462,942	B2	12/2008	Tan et al.
6,396,707	B1	5/2002	Huang et al.	7,488,896	B2	2/2009	Saiki et al.
6,409,073	B1	6/2002	Kaskoun et al.	7,521,284	B2	4/2009	Miranda et al.
6,441,316	B1	8/2002	Kusui	7,642,660	B2	1/2010	Tay et al.
6,441,473	B1	8/2002	Deshmukh	7,663,248	B2	2/2010	Hedler et al.
6,448,665	B1	9/2002	Nakazawa et al.	7,663,250	B2	2/2010	Jeon et al.
6,458,622	B1	10/2002	Keser et al.	7,670,939	B2	3/2010	Topacio et al.
6,458,623	B1	10/2002	Goldmann et al.	7,671,454	B2	3/2010	Seko
6,459,622	B1	10/2002	Ogura et al.	7,692,314	B2	4/2010	Yang et al.
6,462,425	B1	10/2002	Iwasaki et al.	7,732,913	B2	6/2010	Hsieh et al.
6,472,608	B2	10/2002	Nakayama et al.	7,750,457	B2	7/2010	Seko
6,495,397	B2	12/2002	Kubota et al.	7,790,509	B2	9/2010	Gerber
6,510,976	B2	1/2003	Hwee et al.	7,791,211	B2	9/2010	Chen et al.
6,518,674	B2	2/2003	Interrante et al.	7,847,399	B2	12/2010	Masumoto
6,518,678	B2	2/2003	James et al.	7,847,417	B2	12/2010	Araki et al.
6,550,666	B2	4/2003	Chew et al.	7,851,928	B2	12/2010	Gallegos et al.
6,556,268	B1	4/2003	Lee et al.	7,898,083	B2	3/2011	Castro
6,563,712	B2	5/2003	Akram et al.	7,902,660	B1	3/2011	Lee et al.
6,573,610	B1	6/2003	Tsai	7,902,678	B2	3/2011	Ohuchi et al.
6,577,014	B2	6/2003	Shen et al.	7,902,679	B2	3/2011	Lin et al.
6,578,754	B1	6/2003	Tung	7,932,170	B1	4/2011	Huemoeller et al.
6,592,019	B2	7/2003	Tung	7,947,602	B2	5/2011	Ito et al.
6,600,234	B2	7/2003	Kuwabara et al.	7,973,406	B2	7/2011	Pendse
6,608,388	B2	8/2003	Lin et al.	8,129,841	B2	3/2012	Pendse et al.
6,660,560	B2	12/2003	Chaudhuri et al.	8,178,392	B2	5/2012	Choi et al.
6,661,084	B1	12/2003	Peterson et al.	8,188,598	B2	5/2012	Pendse
6,664,483	B2	12/2003	Chong et al.	8,759,972	B2	6/2014	Pendse
6,678,948	B1	1/2004	Benzler et al.	2001/0008309	A1	7/2001	Iijima et al.
6,681,982	B2	1/2004	Tung	2001/0012644	A1	8/2001	Chen
6,707,162	B1	3/2004	Ho et al.	2001/0013423	A1	8/2001	Dalal et al.
6,710,458	B2	3/2004	Seko	2001/0018230	A1	8/2001	Jimarez et al.
6,734,557	B2	5/2004	Taniguchi et al.	2002/0033412	A1	3/2002	Tung
6,737,295	B2	5/2004	Pendse et al.	2002/0041036	A1	4/2002	Smith
6,768,190	B2	7/2004	Yang et al.	2002/0070451	A1	6/2002	Burnette et al.
6,774,474	B1	8/2004	Caletka et al.	2002/0070463	A1	6/2002	Chang et al.
6,774,497	B1	8/2004	Qi et al.	2002/0100610	A1	8/2002	Yasuda et al.
6,780,673	B2	8/2004	Venkateswaran	2002/0121706	A1	9/2002	Tatsuta et al.
6,780,682	B2	8/2004	Pendse	2002/0155637	A1	10/2002	Lee
6,787,918	B1	9/2004	Tsai et al.	2002/0179689	A1	12/2002	Tung
6,798,072	B2	9/2004	Kajiware et al.	2002/0192865	A1	12/2002	Imasu et al.
6,809,262	B1	10/2004	Hsu	2003/0019568	A1	1/2003	Liu et al.
6,818,545	B2	11/2004	Lee et al.	2003/0049411	A1	3/2003	Chaudhuri et al.
6,821,878	B2	11/2004	Danvir et al.	2003/0057551	A1	3/2003	Datta et al.
6,849,944	B2	2/2005	Murtuza et al.	2003/0067084	A1	4/2003	Shintani
6,853,076	B2	2/2005	Datta et al.	2003/0116866	A1	6/2003	Cher 'Khng et al.
6,870,276	B1	3/2005	Moxham et al.	2003/0127734	A1	7/2003	Lee et al.
6,888,255	B2	5/2005	Murtuza et al.	2003/0127747	A1	7/2003	Kajiware et al.
6,913,948	B2	7/2005	Caletka et al.	2003/0157792	A1	8/2003	Tong et al.
6,927,489	B1	8/2005	Yaguchi et al.	2003/0168748	A1	9/2003	Katagiri et al.
6,943,058	B2	9/2005	Chaudhuri et al.	2003/0175146	A1	9/2003	Yeh et al.
6,974,659	B2	12/2005	Su et al.	2004/0026107	A1	2/2004	Caldwell et al.
7,005,585	B2	2/2006	Ishizaki	2004/0027788	A1	2/2004	Chiu et al.
7,005,743	B2	2/2006	Iwatsu et al.	2004/0035909	A1	2/2004	Yeh et al.
7,005,750	B2	2/2006	Liu	2004/0046263	A1	3/2004	Harper et al.
7,049,705	B2	5/2006	Huang	2004/0046264	A1	3/2004	Ho et al.
7,057,284	B2	6/2006	Chauhan et al.	2004/0056341	A1	3/2004	Endo et al.
7,064,435	B2	6/2006	Chung et al.	2004/0105223	A1	6/2004	Okada et al.
7,098,407	B2	8/2006	Kim et al.	2004/0108135	A1	6/2004	Ashida
7,101,781	B2	9/2006	Ho et al.	2004/0126927	A1	7/2004	Lin et al.
7,102,222	B2	9/2006	Kuo et al.	2004/0210122	A1	10/2004	Sieburg
7,102,239	B2	9/2006	Pu et al.	2004/0232560	A1	11/2004	Su
7,112,524	B2	9/2006	Hsu et al.	2004/0232562	A1	11/2004	Hortaleza et al.
7,164,208	B2	1/2007	Kainou et al.	2005/0046041	A1	3/2005	Tsai
7,173,828	B2	2/2007	Lin et al.	2005/0082654	A1	4/2005	Humpston et al.
7,183,493	B2	2/2007	Garcia et al.	2005/0103516	A1	5/2005	Kaneyuki
7,224,073	B2	5/2007	Kim	2005/0224991	A1	10/2005	Yeo
7,242,099	B2	7/2007	Lin et al.	2005/0248037	A1	11/2005	Hung et al.
7,271,484	B2	9/2007	Reiss et al.	2006/0131758	A1	6/2006	Dao
7,294,451	B2	11/2007	Chiu et al.	2006/0192294	A1	8/2006	Lee
7,294,457	B2	11/2007	Kukolj et al.	2006/0202331	A1	9/2006	Hu
7,294,929	B2	11/2007	Miyazaki	2006/0216860	A1	9/2006	Pendse
				2006/0255473	A1	11/2006	Pendse
				2007/0200234	A1	8/2007	Gerber et al.
				2007/0259514	A1	11/2007	Otremba
				2008/0088013	A1	4/2008	Chew et al.

(56)

**References Cited****U.S. PATENT DOCUMENTS**

2008/0093749	A1	4/2008	Gerber et al.
2008/0179740	A1	7/2008	Liao
2008/0213941	A1	9/2008	Pendse
2008/0277802	A1	11/2008	Tsai et al.
2009/0045507	A1	2/2009	Pendse et al.
2009/0057378	A1	3/2009	Hwang et al.
2009/0108445	A1	4/2009	Liang
2009/0114436	A1	5/2009	Chen et al.
2009/0146303	A1	6/2009	Kwon
2009/0152716	A1	6/2009	Sohara
2009/0191329	A1	7/2009	Wang
2009/0288866	A1	11/2009	Tsai et al.
2009/0308647	A1	12/2009	Liao
2010/0139965	A1	6/2010	Wang et al.
2011/0049703	A1	3/2011	Hsu et al.
2011/0241203	A1	10/2011	Nakasato et al.
2013/0214409	A1	8/2013	Pagaila et al.
2013/0277830	A1	10/2013	Yu et al.

**FOREIGN PATENT DOCUMENTS**

JP	6503687	4/1994
JP	09-097791	8/1997
JP	10-256307	9/1998
JP	10-256315	9/1998
JP	11145176	5/1999
JP	11233571	8/1999
JP	11330162	11/1999
JP	2000-031204	1/2000
JP	2000-133667	12/2000
JP	2000-349194	12/2000
JP	2001156203	6/2001
JP	2001-332583	11/2001
JP	2001351945	12/2001
JP	2002270732	9/2002
JP	2004-221205	5/2004
JP	2005109187	5/2004
JP	2004165283	6/2004
JP	2005333166	12/2005
JP	2009231657	10/2009
JP	2010018534	5/2010
KR	1998-79438	11/1998
KR	2000-62333	10/2000
SG	100817	7/2004
TW	530398	5/2003

WO	9306964	A1	4/1993
WO	0013228		3/2000
WO	03071842	A1	8/2003
WO	2010067610		6/2010

**OTHER PUBLICATIONS**

Gerber et al., "Next Generation Fine Pitch Cu Pillar Technology—Enabling Next Generation Silicon Nodes", Electronic Components and Technology Conference, pp. 612-618, 2011.

He et al., "All-Copper Chip-to-Substrate Interconnects Part II. Modeling and Design", Journal of the Electrochemical Society, 155(4):D314-D322, 2008.

Heinen et al., "Multichip Assembly with Flipped Integrated Circuits", IEEE Transactions on Components Hybrids and Manufacturing Technology, vol. 12, No. 4, pp. 650-657, Dec. 1989.

Lau et al., "A New Thermal-Fatigue Life Prediction Model for Wafer Level Chip Scale Package (WLCSP) Solder Joints", Transactions of the ASME, vol. 124, pp. 112-120, Sep. 2002.

Love et al., "Wire Interconnect Technology, A New High-Reliability Tight-Pitch Interconnect Technology", Karl Suss, pp. 1-6, 1999.

Pendse et al., "Bon-on-Lead: A Novel Flip Chip Interconnection Technology for Fine Effective Pitch and High I/O Density", Electronic Components and Technology Conference, pp. 16-23, 2006.

Powell et al., "Flip-Chip on FR-4 Integrated Circuit Packaging", pp. 182-186, IEEE 1993.

Schubert et al., "Numerical and Experimental Investigations of Large IC Flip Chip Attach", Electronic Components and Technology Conference, pp. 1338-1346 IEEE 2000.

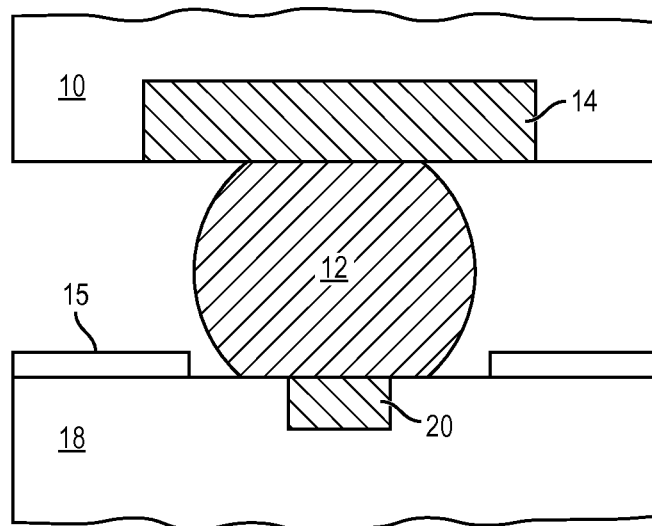
Son, Ho Young et al., "Studies on the Thermal Cycling Reliability of Fine Pitch Cu/SnAg Double-Bump Flip Chip Assemblies on Organic Substrates: Experimental Results and Numerical Analysis", Electronic Components and Technology Conference, 2008, pp. 2035-2043.

Yamada, Hiroshi et al., "Advanced copper column based solder bump for flip-chip interconnection", International Symposium on Microelectronics, 1997, pp. 417-422, The British Library—"The world's knowledge".

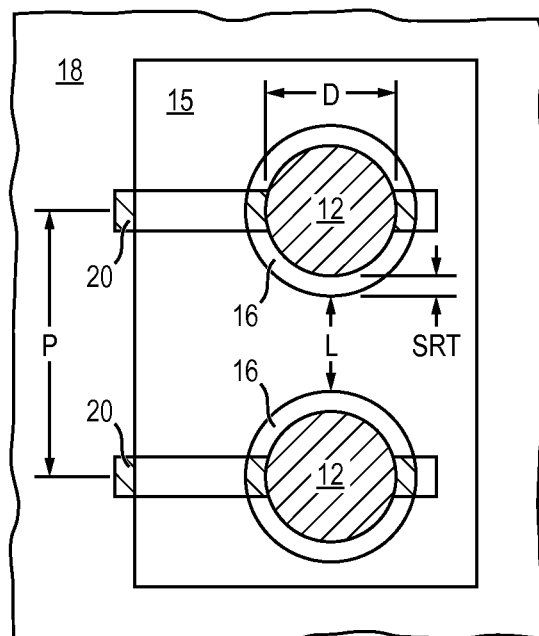
Yamada, Hiroshi et al., "A fine pitch and high aspect ratio bump array for flip-chip interconnection", Int'l Electronics Manufacturing Technology Symposium, 1992, pp. 288-292, IEEE/CHMT.

Lu, H. et al., "Predicting Optimal Process Conditions for Flip-Chip Assembly Using Copper Column Bumped Dies", Electronics Packaging Technology Conference, 2002, pp. 338-343.

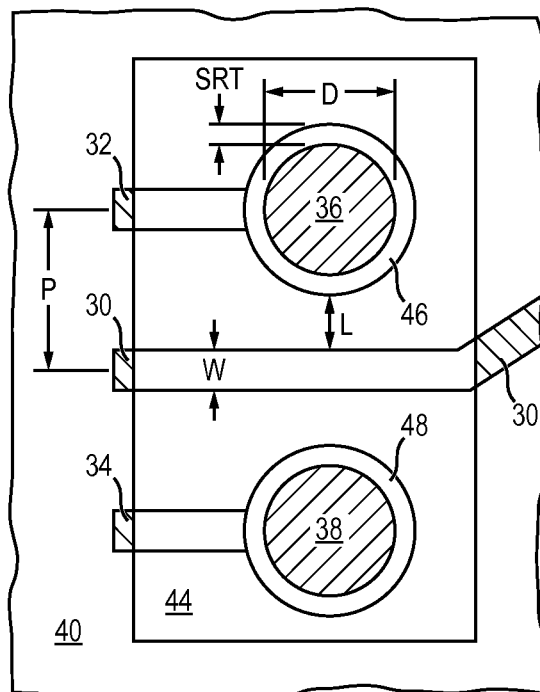
Kawahara, Toshimi, "SuperCSP", IEEE Transactions on Advanced Packaging, May 2000, pp. 215-219, vol. 23, No. 2.



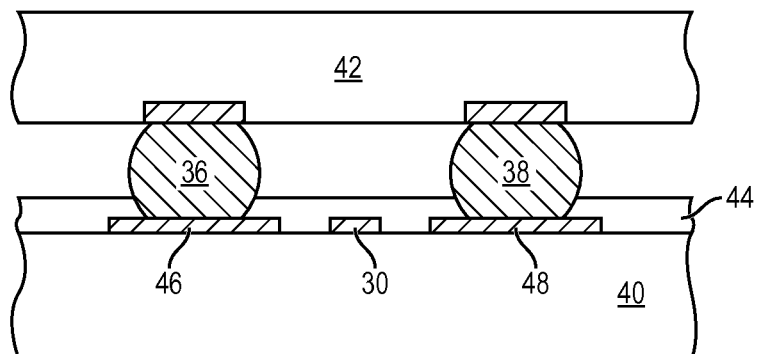
*FIG. 1*  
(PRIOR ART)



*FIG. 2*  
(PRIOR ART)



*FIG. 3a*  
(PRIOR ART)



*FIG. 3b*  
(PRIOR ART)

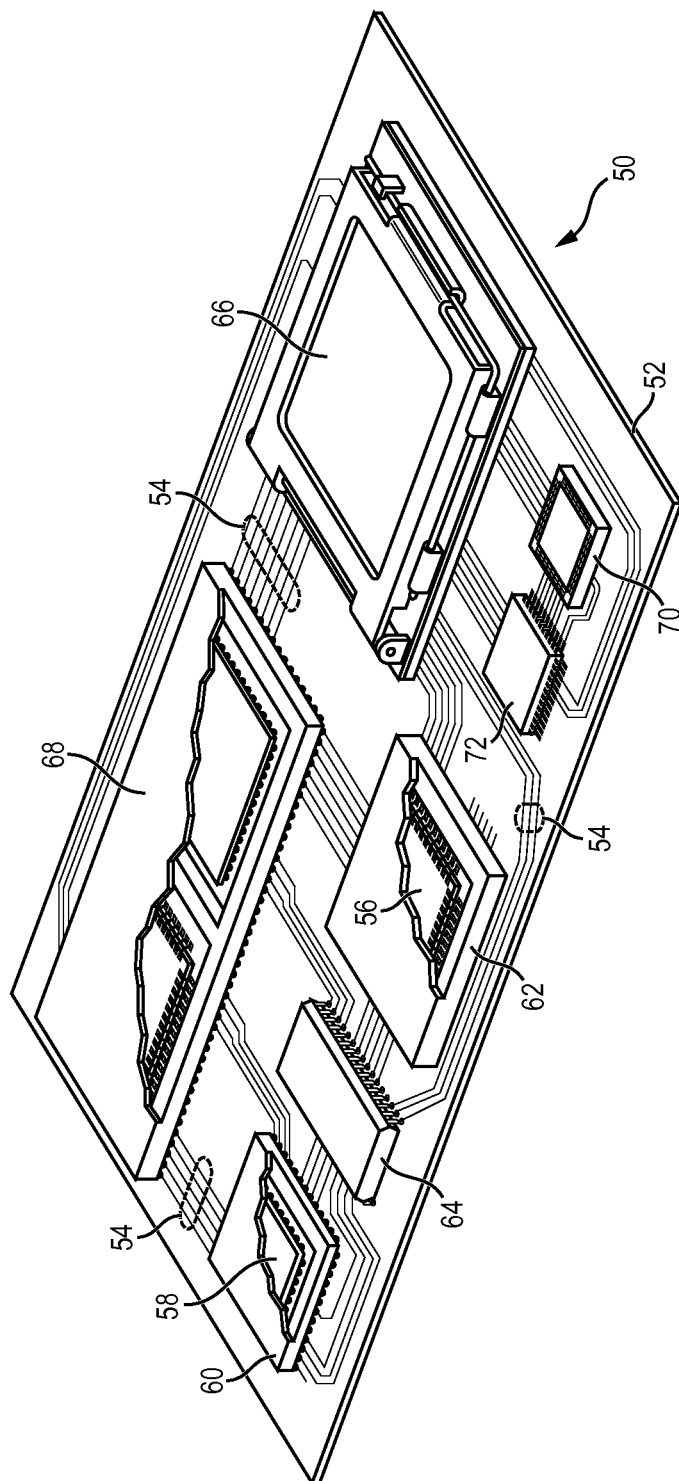


FIG. 4

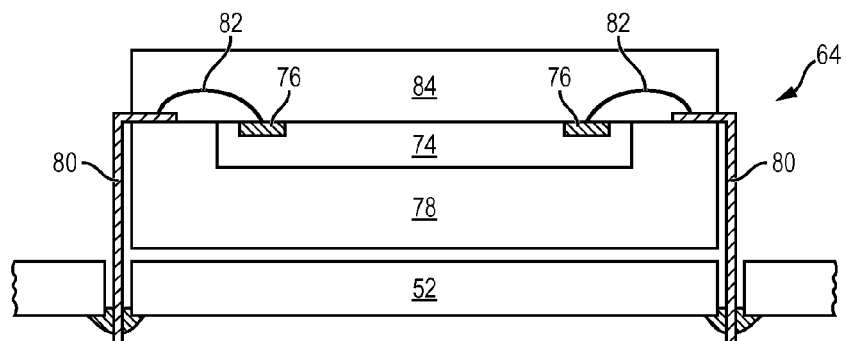


FIG. 5a

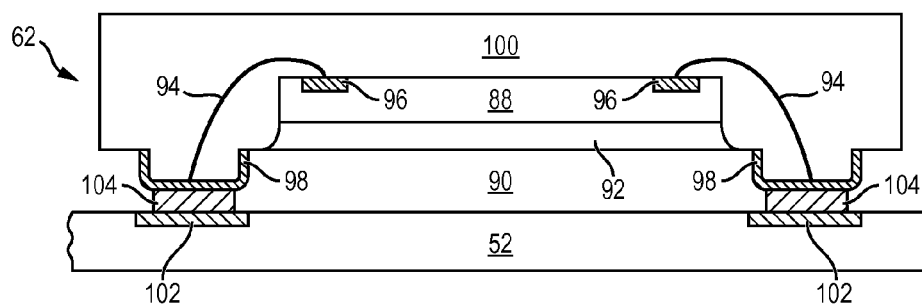


FIG. 5b

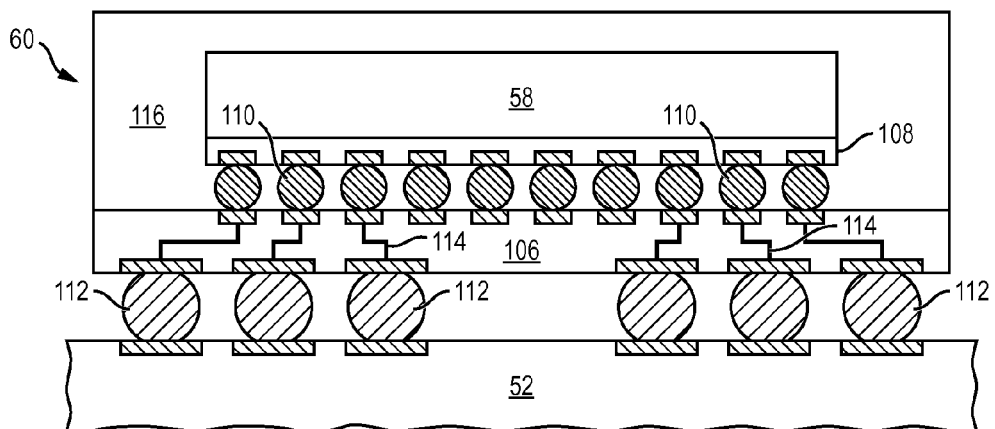


FIG. 5c



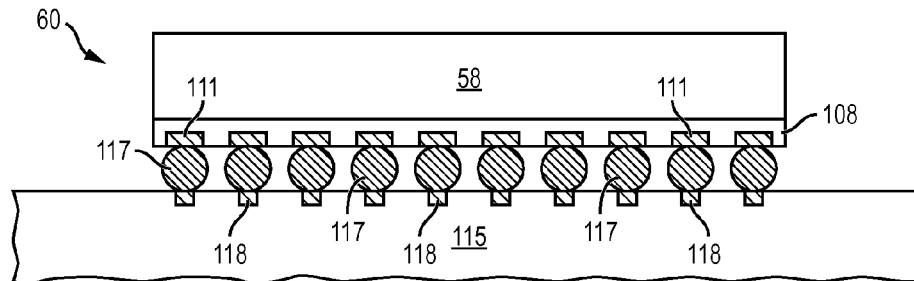


FIG. 5d

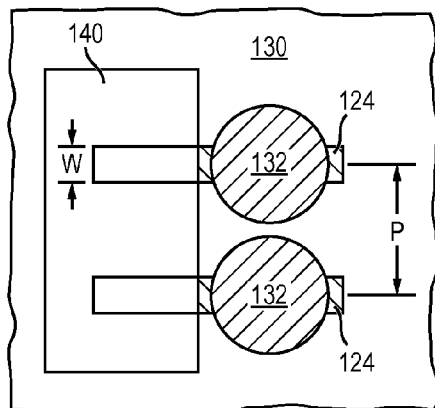


FIG. 6a

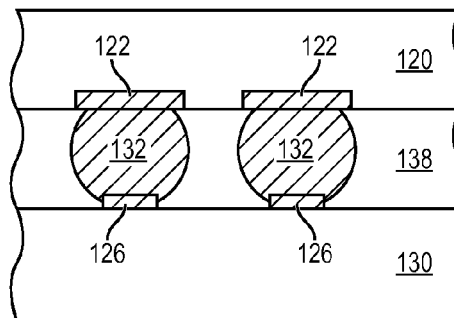


FIG. 6b

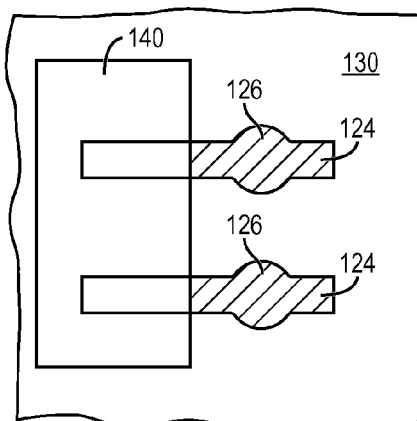


FIG. 7a

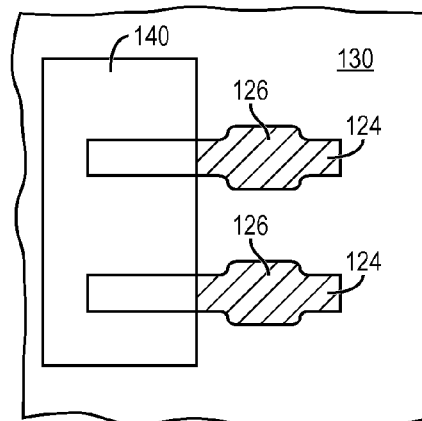


FIG. 7b

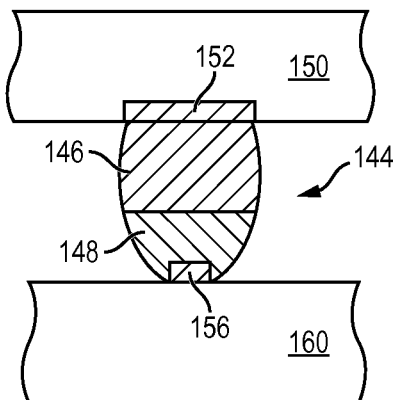


FIG. 8

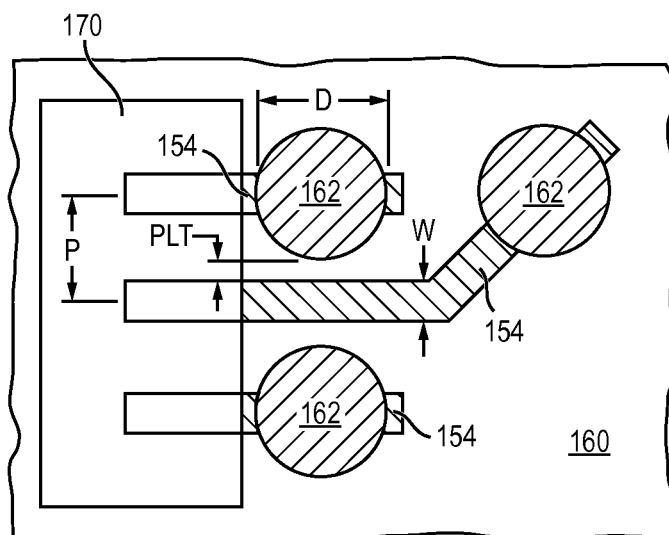


FIG. 9a

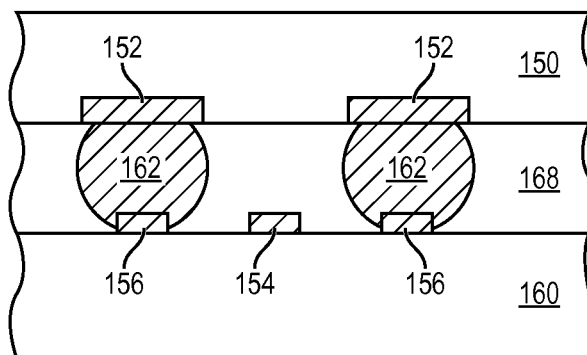


FIG. 9b

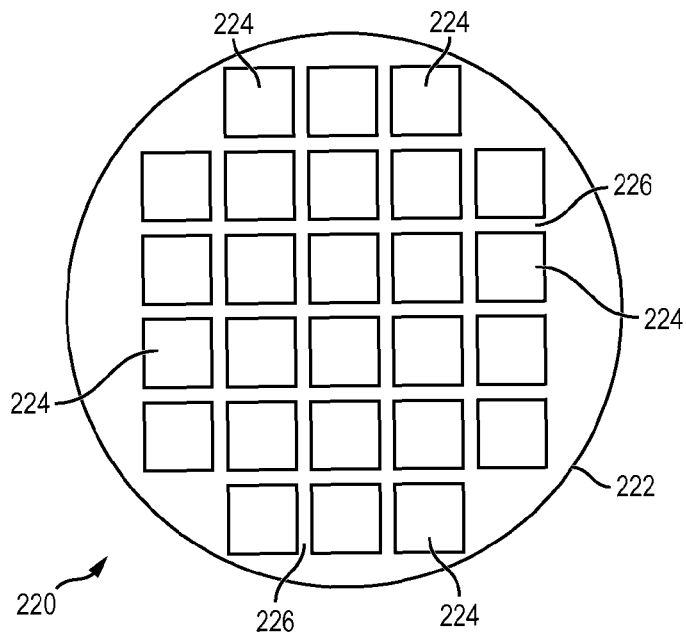


FIG. 10a

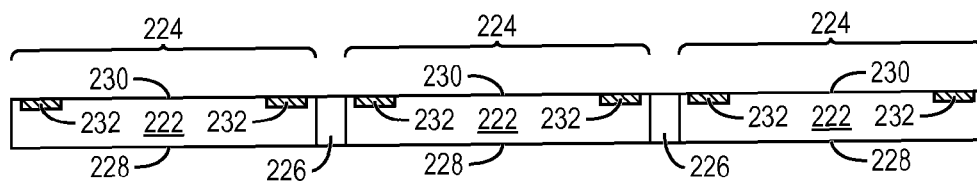


FIG. 10b

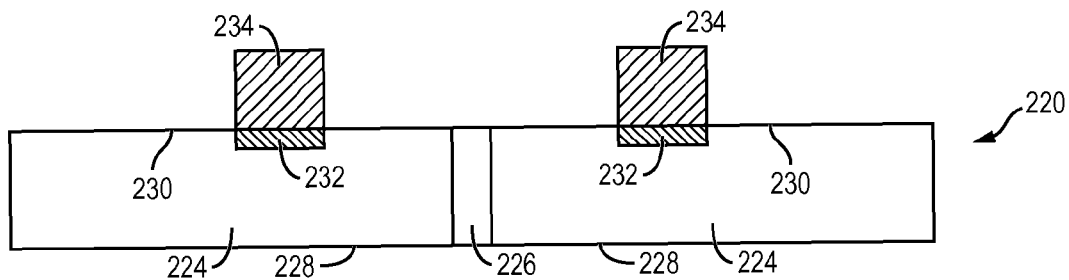


FIG. 10c

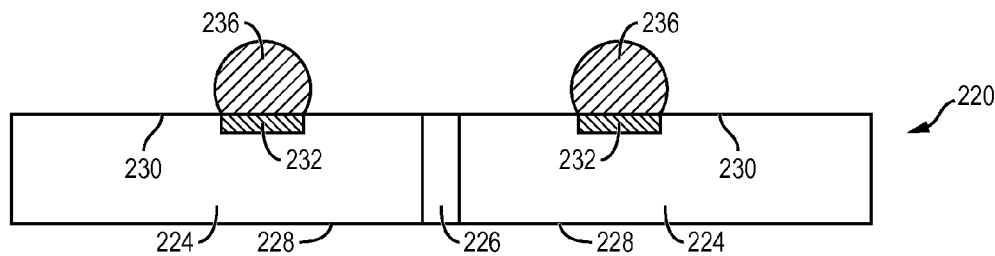


FIG. 10d

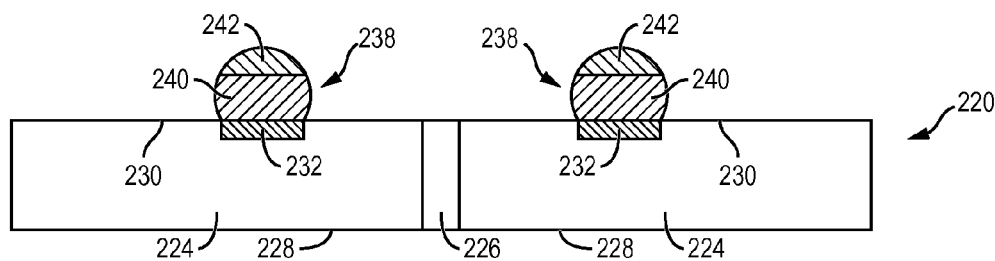


FIG. 10e

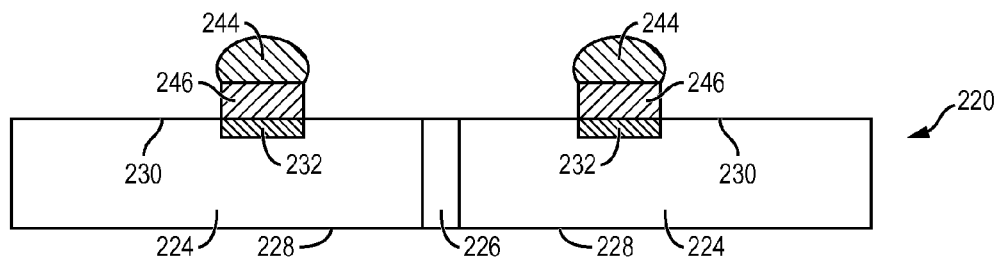


FIG. 10f

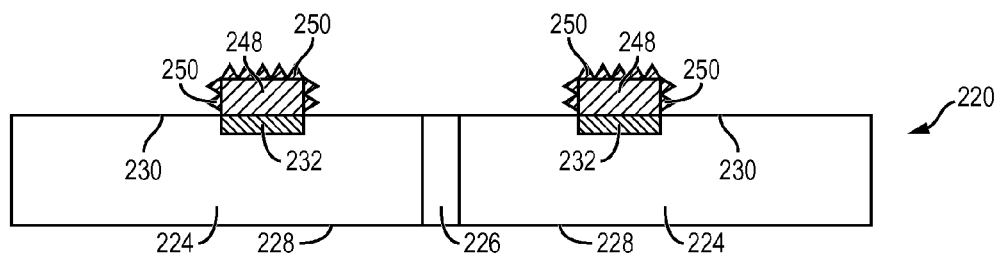


FIG. 10g

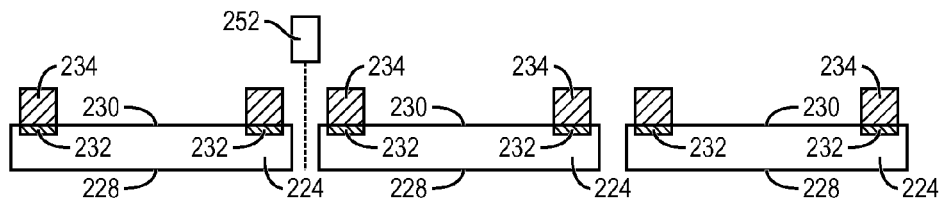


FIG. 10h

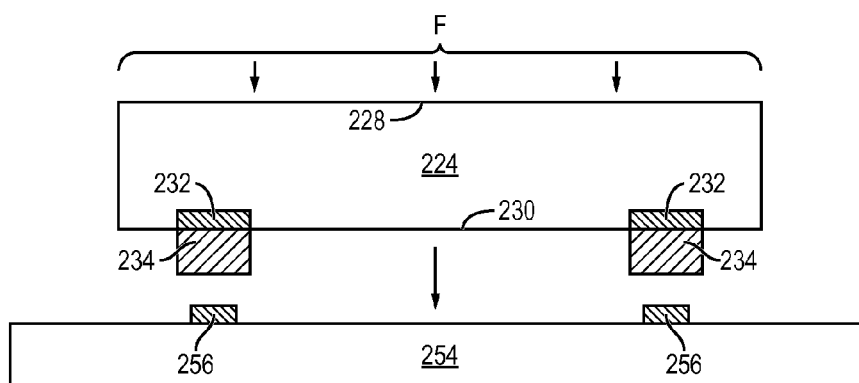


FIG. 11a

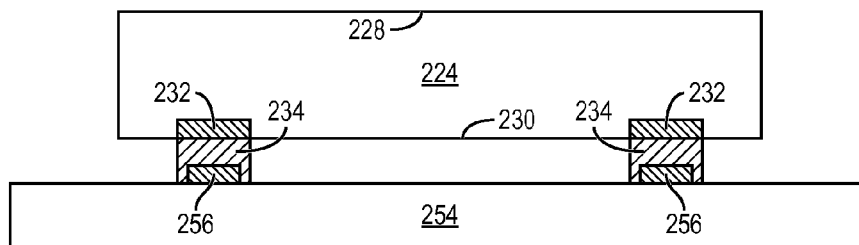


FIG. 11b

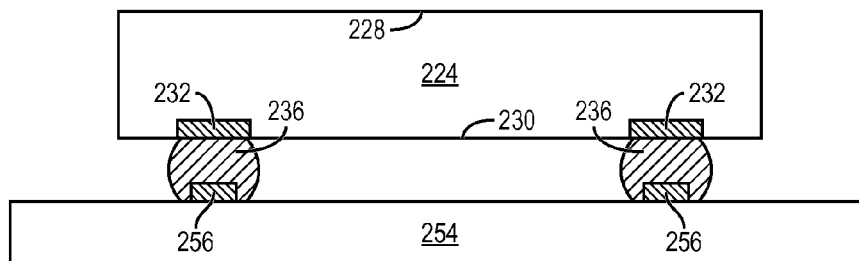


FIG. 11c

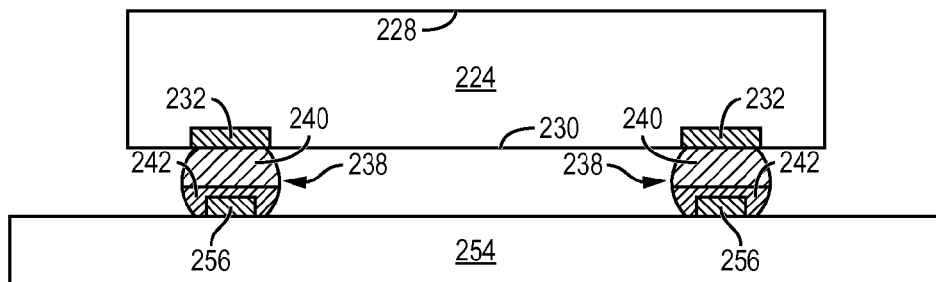


FIG. 11d

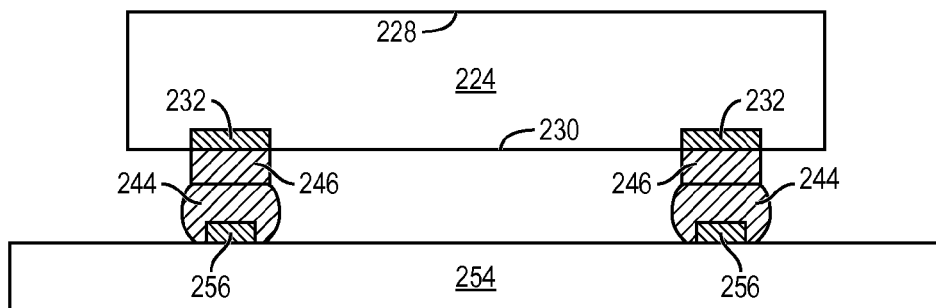


FIG. 11e

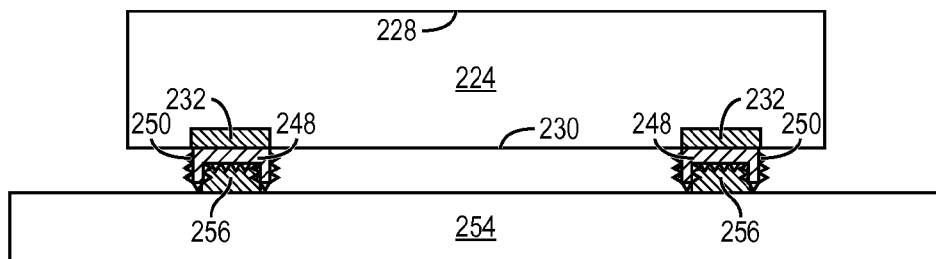


FIG. 11f

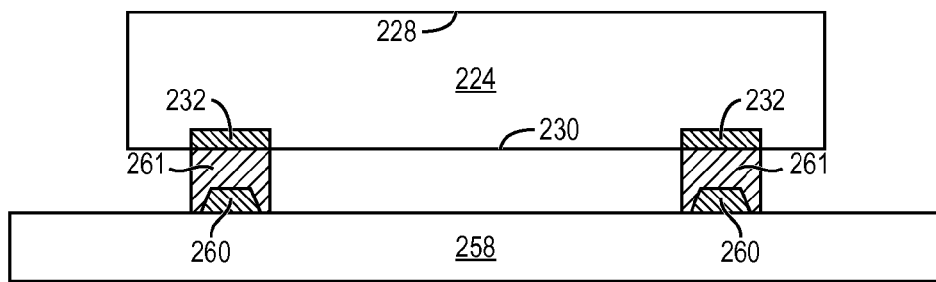


FIG. 11g

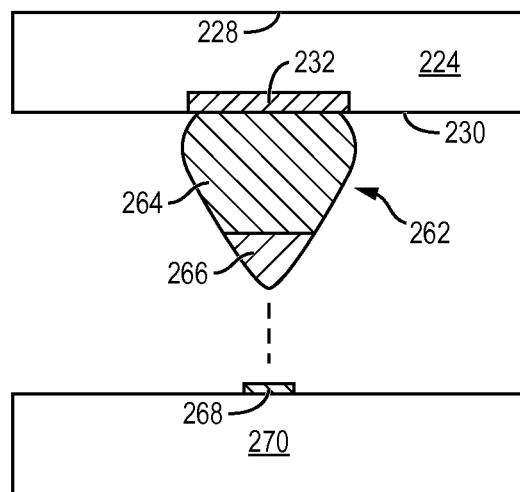


FIG. 12a

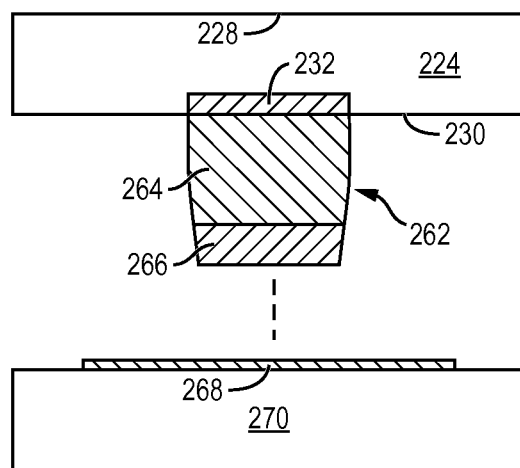


FIG. 12b

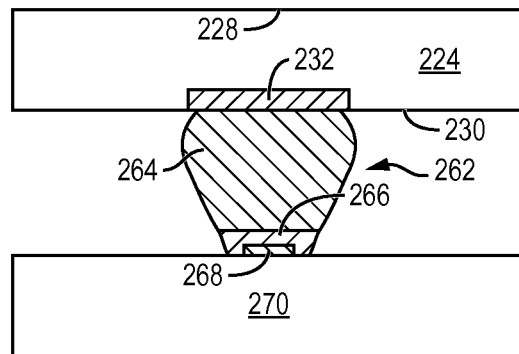


FIG. 12c

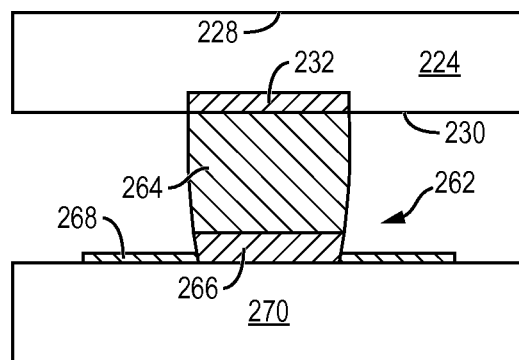


FIG. 12d

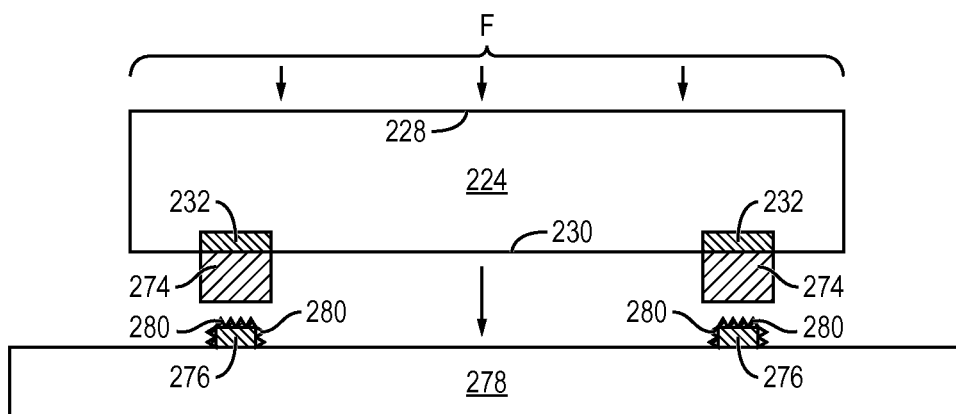


FIG. 13a



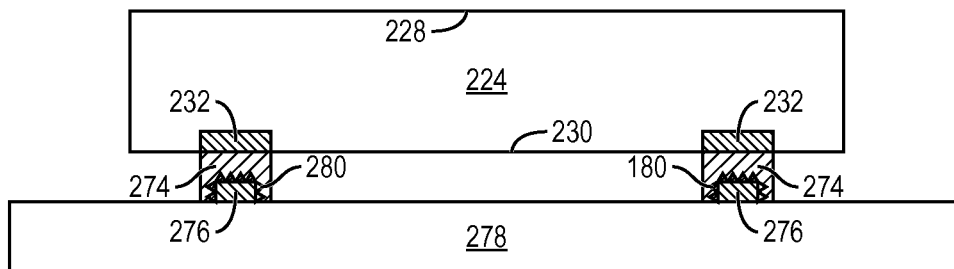


FIG. 13b

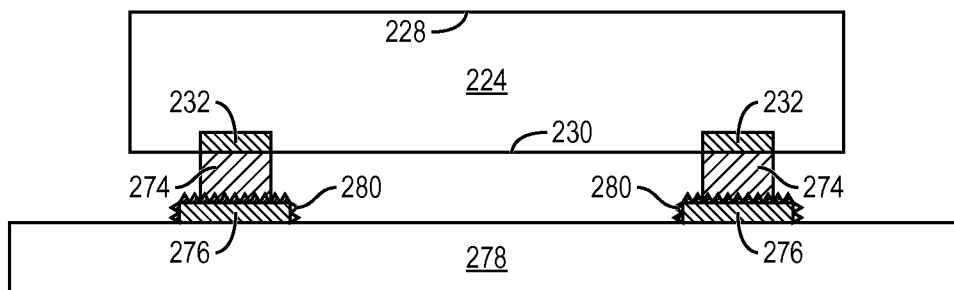


FIG. 13c

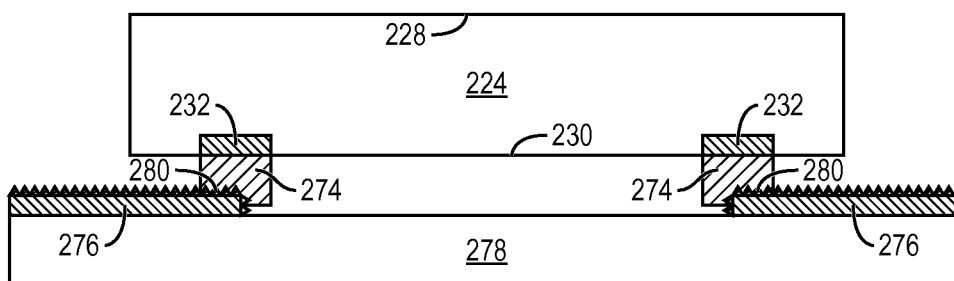


FIG. 13d

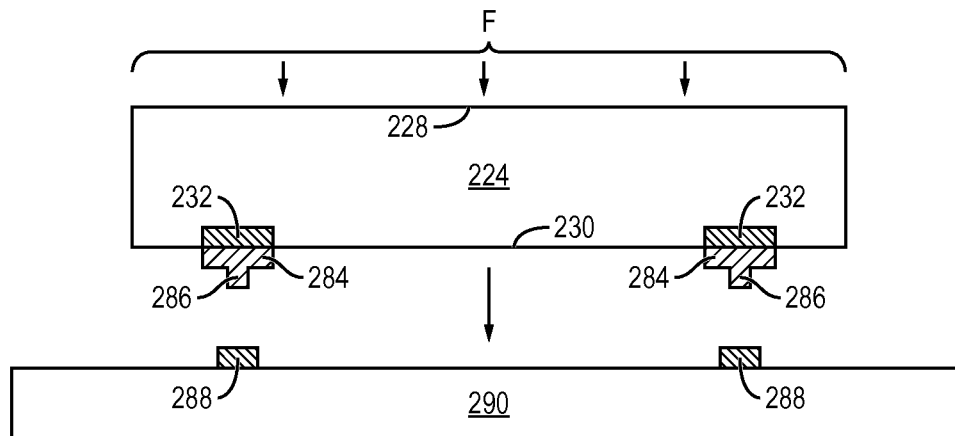


FIG. 14a

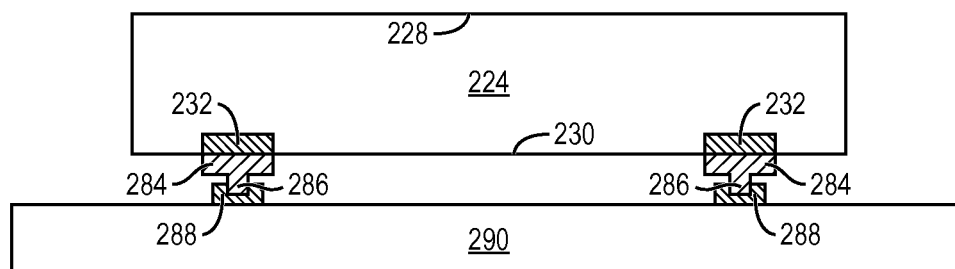


FIG. 14b

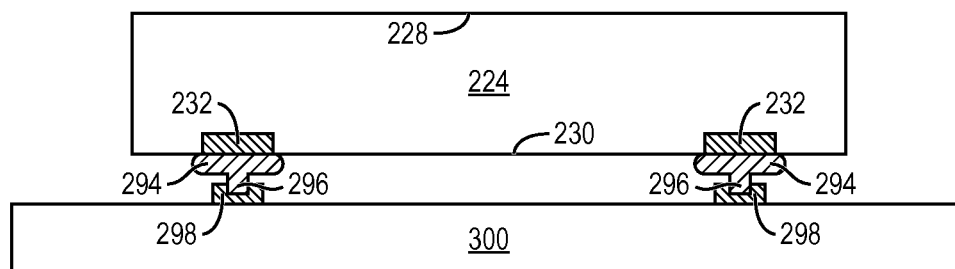


FIG. 14c

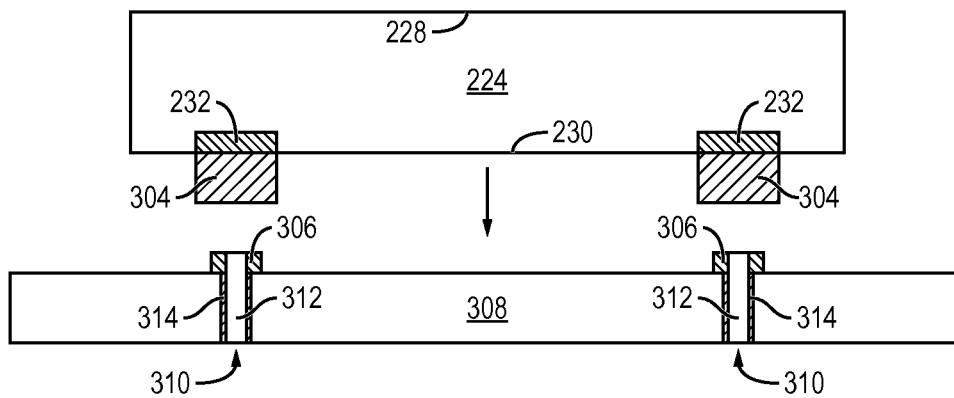


FIG. 15a

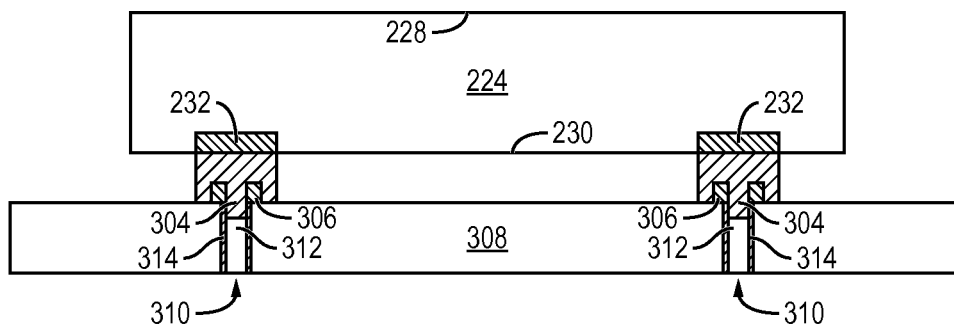
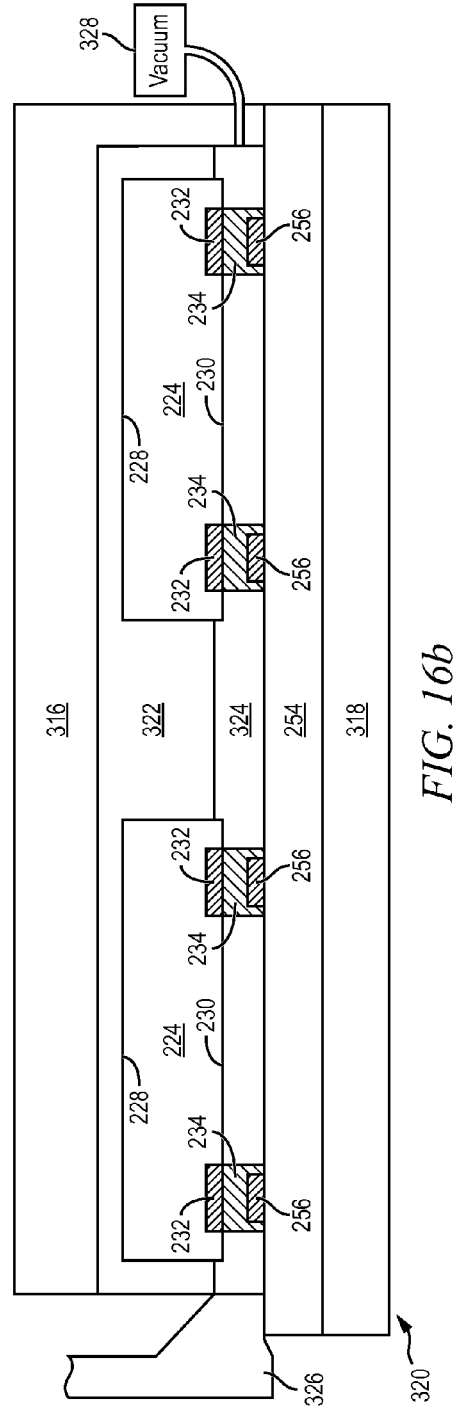
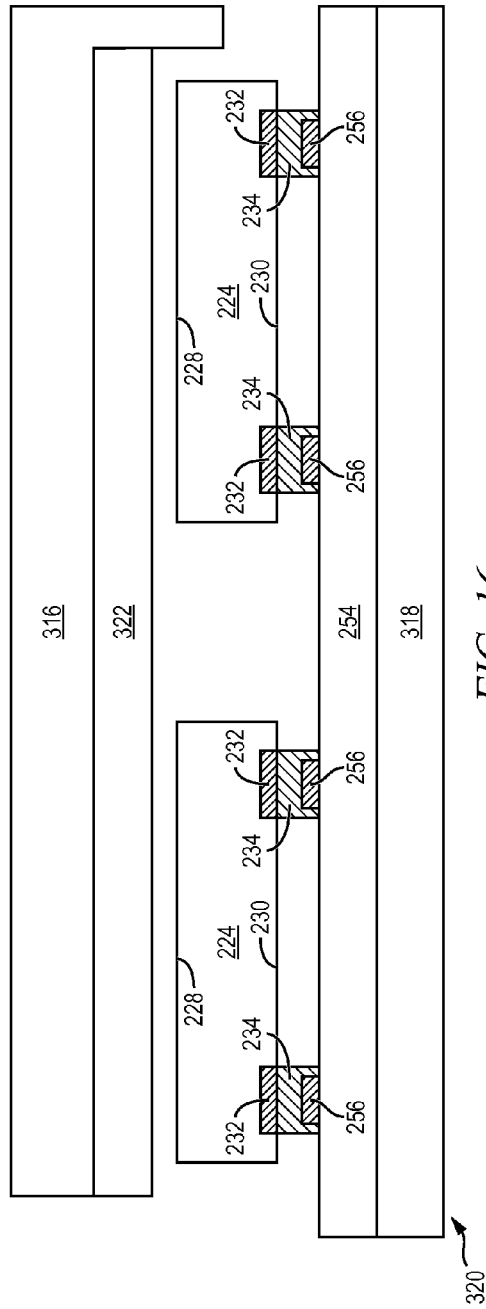
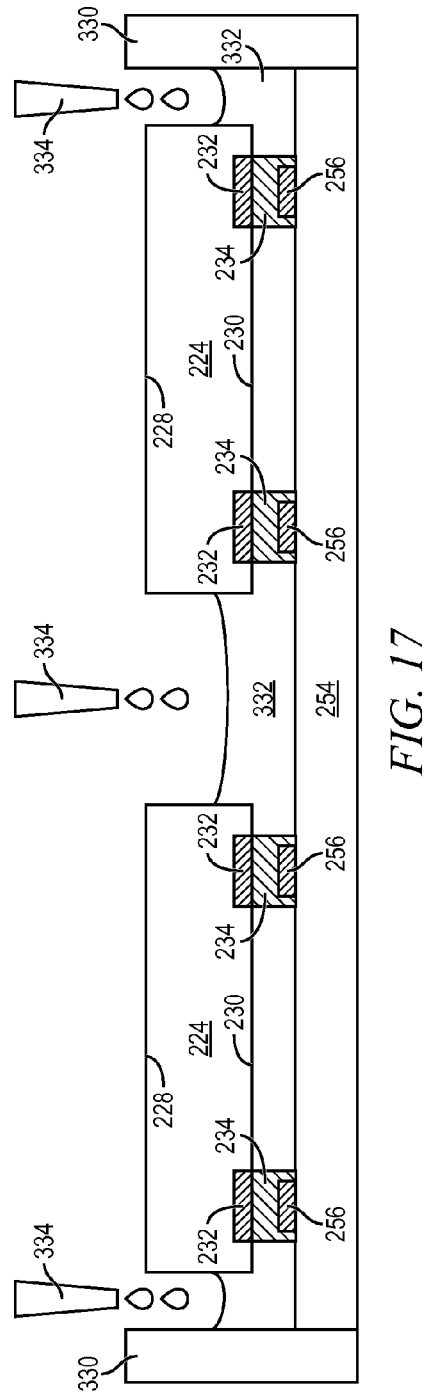
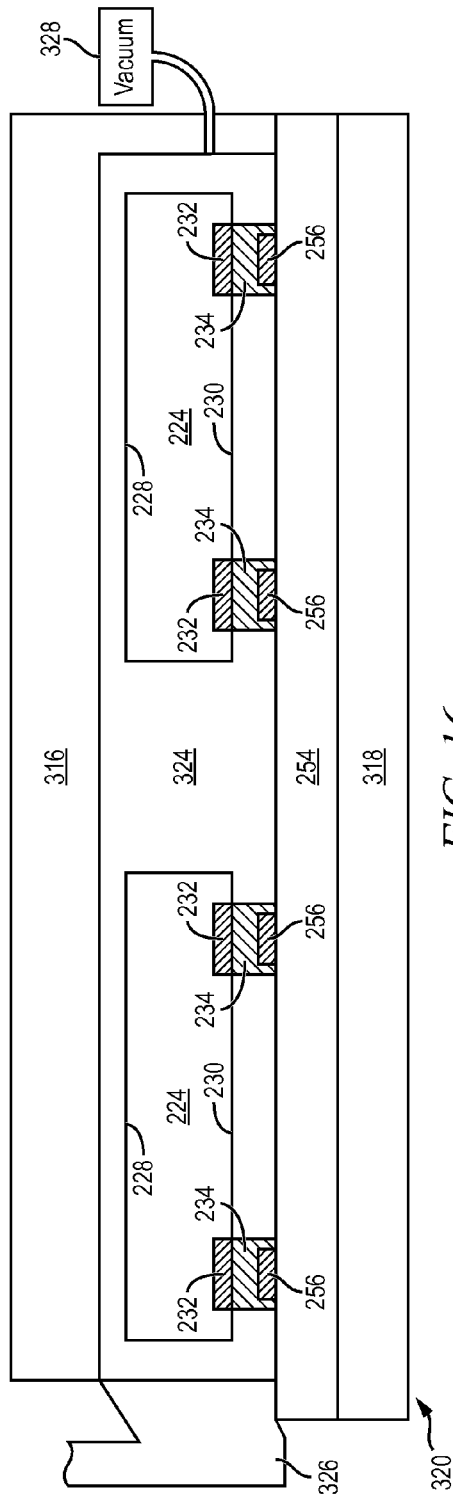


FIG. 15b





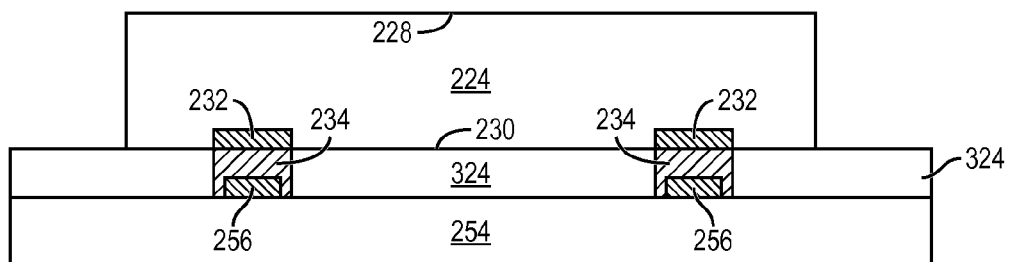


FIG. 18

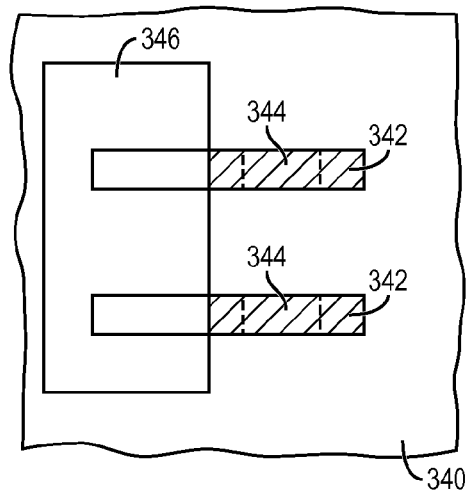


FIG. 19a

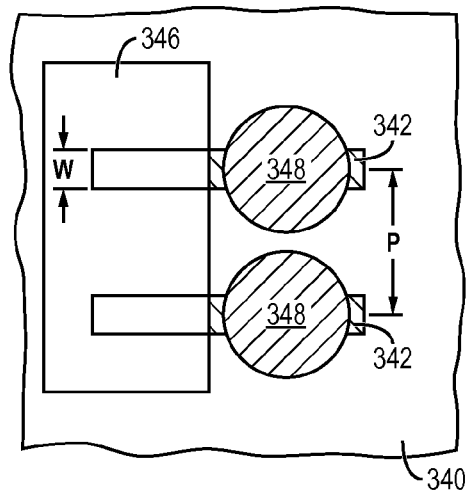


FIG. 19b

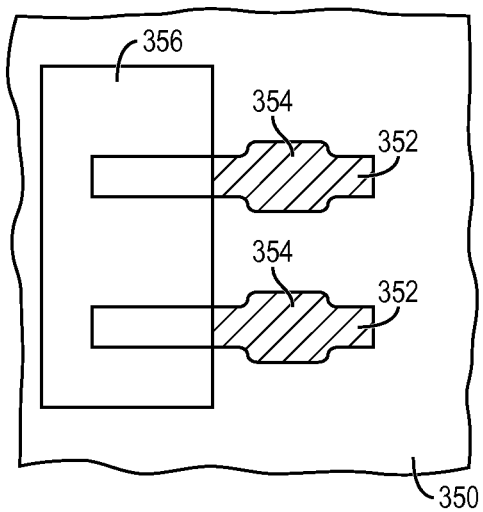


FIG. 19c

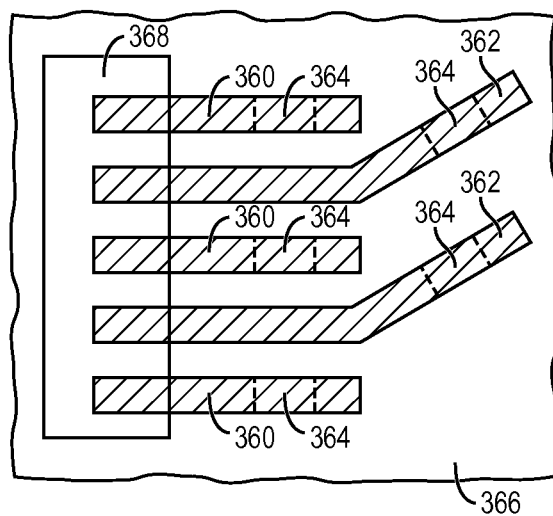


FIG. 19d

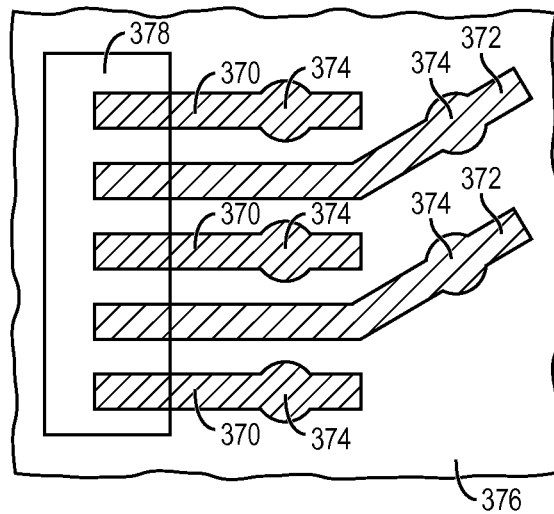


FIG. 19e

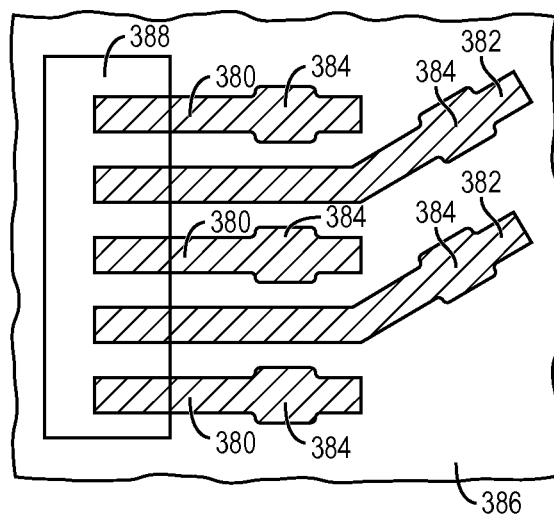


FIG. 19f



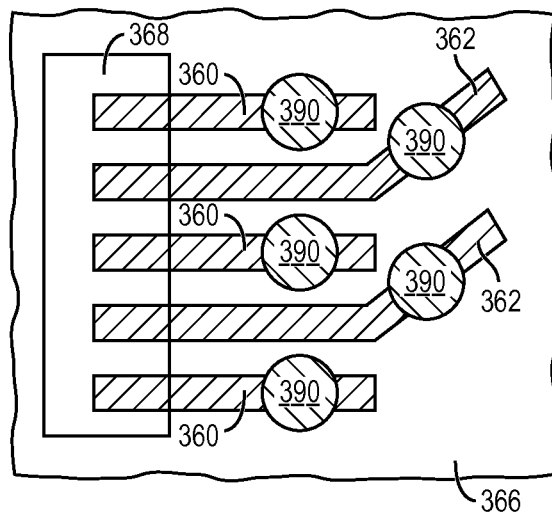


FIG. 19g

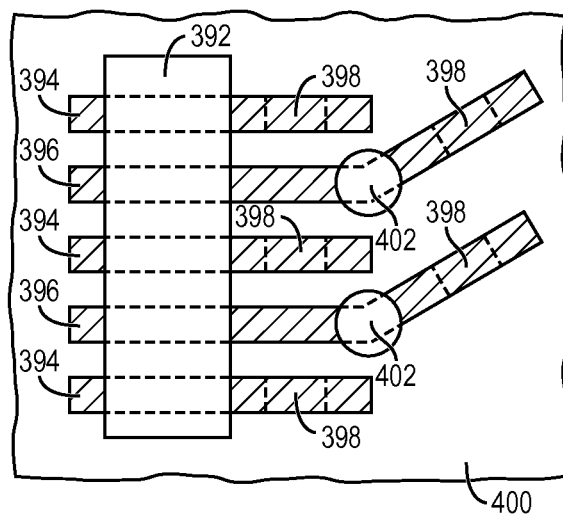


FIG. 20a

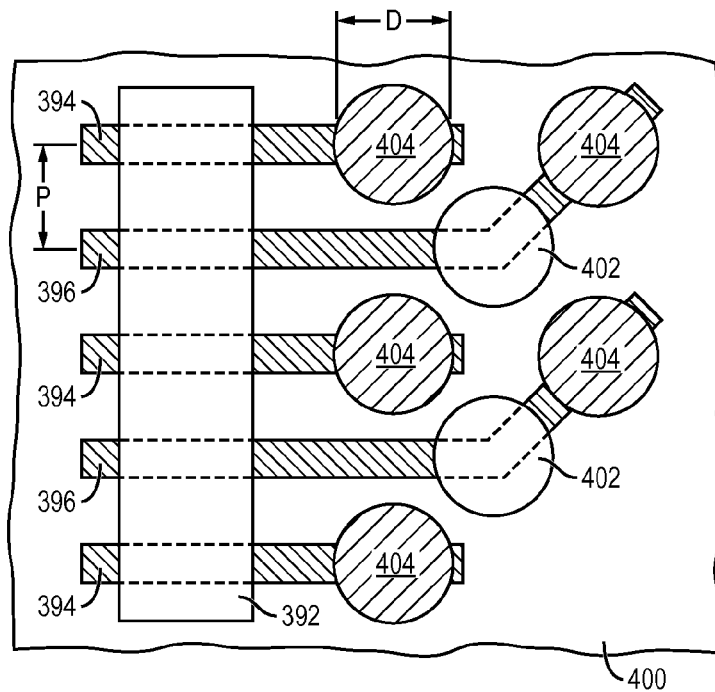


FIG. 20b

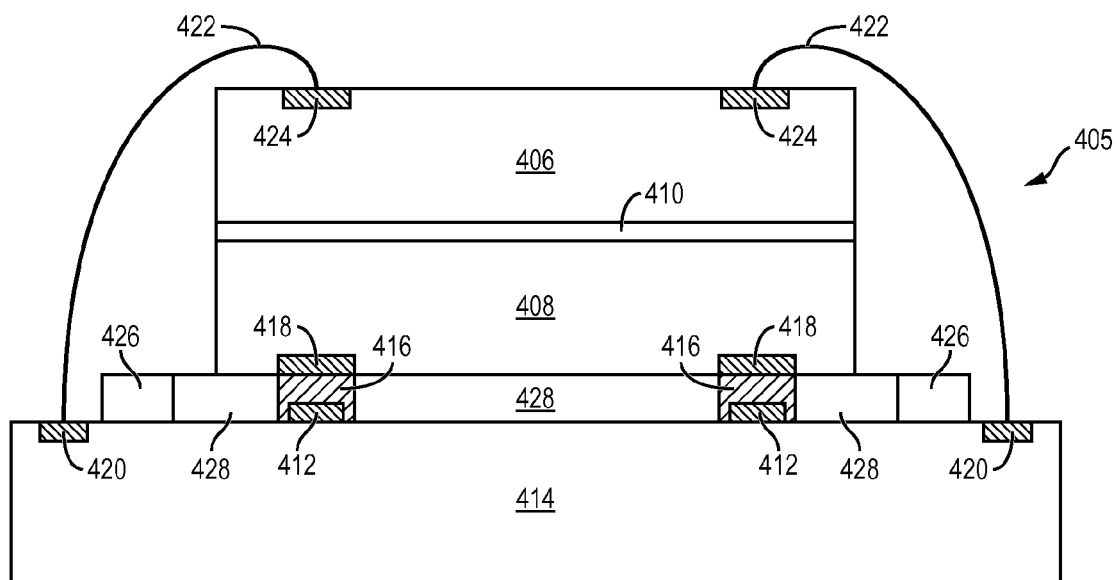


FIG. 21

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# SEMICONDUCTOR DEVICE AND METHOD OF SELF-CONFINEMENT OF CONDUCTIVE BUMP MATERIAL DURING REFLOW WITHOUT SOLDER MASK

## CLAIM OF DOMESTIC PRIORITY

The present application is a continuation of U.S. patent application Ser. No. 12/969,467, now U.S. Pat. No. 9,029,196, filed Dec. 15, 2010, which is a continuation-in-part of U.S. patent application Ser. No. 12/471,180, now U.S. Pat. No. 8,026,128, filed May 22, 2009, and reissued as U.S. Pat. No. RE44,579, which claims the benefit of U.S. Provisional Application No. 61/141,791, filed Dec. 31, 2008, and U.S. application Ser. No. 12/471,180 is a continuation-in-part of U.S. patent application Ser. No. 12/062,293, now U.S. Pat. No. 7,700,407, filed Apr. 3, 2008, and reissued as U.S. Pat. No. RE44,355, which is a division of U.S. patent application Ser. No. 10/985,654, now U.S. Pat. No. 7,368,817, filed Nov. 10, 2004, which claims the benefit of U.S. Provisional Application No. 60/533,918, filed Dec. 31, 2003, and U.S. Provisional Application No. 60/518,864, filed Nov. 10, 2003, and U.S. patent application Ser. No. 12/969,467, filed Dec. 15, 2010, is a continuation-in-part of U.S. patent application Ser. No. 12/757,889, now U.S. Pat. No. 8,318,537, filed Apr. 9, 2010, which is a continuation of U.S. patent application Ser. No. 11/388,755, now abandoned, filed Mar. 24, 2006, which claims the benefit of U.S. Provisional Application No. 60/665,208, filed Mar. 25, 2005. All of the above-referenced applications are incorporated herein by reference.

## FIELD OF THE INVENTION

The present invention relates in general to semiconductor devices and, more particularly, to a semiconductor device and method of providing self-confinement of conductive bump material during reflow without use of a solder mask.

## BACKGROUND OF THE INVENTION

Semiconductor devices are commonly found in modern electronic products. Semiconductor devices vary in the number and density of electrical components. Discrete semiconductor devices generally contain one type of electrical component, e.g., light emitting diode (LED), small signal transistor, resistor, capacitor, inductor, and power metal oxide semiconductor field effect transistor (MOSFET). Integrated semiconductor devices typically contain hundreds to millions of electrical components. Examples of integrated semiconductor devices include microcontrollers, microprocessors, charged-coupled devices (CCDs), solar cells, and digital micro-mirror devices (DMDs).

Semiconductor devices perform a wide range of functions such as signal processing, high-speed calculations, transmitting and receiving electromagnetic signals, controlling electronic devices, transforming sunlight to electricity, and creating visual images for television displays. Semiconductor devices are found in the fields of entertainment, communications, power conversion, networks, computers, and consumer products. Semiconductor devices are also found in military applications, aviation, automotive, industrial controllers, and office equipment.

Semiconductor devices exploit the electrical properties of semiconductor materials. The atomic structure of semiconductor material allows its electrical conductivity to be manipulated by the application of an electric field or base current or through the process of doping. Doping introduces

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impurities into the semiconductor material to manipulate and control the conductivity of the semiconductor device.

A semiconductor device contains active and passive electrical structures. Active structures, including bipolar and field effect transistors, control the flow of electrical current. By varying levels of doping and application of an electric field or base current, the transistor either promotes or restricts the flow of electrical current. Passive structures, including resistors, capacitors, and inductors, create a relationship between voltage and current necessary to perform a variety of electrical functions. The passive and active structures are electrically connected to form circuits, which enable the semiconductor device to perform high-speed calculations and other useful functions.

Semiconductor devices are generally manufactured using two complex manufacturing processes, i.e., front-end manufacturing, and back-end manufacturing, each involving potentially hundreds of steps. Front-end manufacturing involves the formation of a plurality of die on the surface of a semiconductor wafer. Each die is typically identical and contains circuits formed by electrically connecting active and passive components. Back-end manufacturing involves singulating individual die from the finished wafer and packaging the die to provide structural support and environmental isolation.

One goal of semiconductor manufacturing is to produce smaller semiconductor devices. Smaller devices typically consume less power, have higher performance, and can be produced more efficiently. In addition, smaller semiconductor devices have a smaller footprint, which is desirable for smaller end products. A smaller die size can be achieved by improvements in the front-end process resulting in die with smaller, higher density active and passive components. Back-end processes may result in semiconductor device packages with a smaller footprint by improvements in electrical interconnection and packaging materials.

FIG. 1 illustrates a portion of flipchip type semiconductor device **10** with interconnect **12** metallurgically and electrically connected between bump pad **14** and trace line **20** using solder mask **15**. A circular solder mask or registration opening (SRO) **16** is formed over substrate **18** to expose trace line **20**, as shown in FIG. 2. Trace line **20** is a straight conductor with optional bump pad for mating to interconnect **12**. SRO **16** confines the conductive bump material on the bump pad of trace line **20** during reflow and prevents the molten bump material from leeching onto the trace lines, which can cause electrical shorts to adjacent structures. SRO **16** is made larger than the trace line or bump pad. SRO **16** is typically circular in shape and made as small as possible to reduce the pitch of trace line **20** and increase routing density.

In typical design rules, the minimum escape pitch of trace line **20** is limited by the fact that SRO **16** must be at least as large as the base diameter (D) of interconnect **12** plus a solder mask registration tolerance (SRT). In addition, a minimum ligament (L) of solder mask material is needed between adjacent openings by virtue of the limits of the solder mask application process. More specifically, the minimum escape pitch is defined as  $P=D+2*SRT+L$ . In one embodiment, D is 100 micrometers ( $\mu\text{m}$ ), SRT is 10  $\mu\text{m}$ , and L is 60  $\mu\text{m}$ , hence, the minimum escape pitch is  $100+2*10+60=180\ \mu\text{m}$ .

FIGS. 3a and 3b show a top view and cross-sectional view of another conventional arrangement with trace line **30** routed between traces lines **32** and **34** and bumps **36** and **38** on substrate **40**. Bumps **36** and **38** electrically connect semiconductor die **42** to substrate **40**. Solder mask **44** overlays bump pads **46** and **48**. The minimum escape pitch of trace line **30** is defined by  $P=D/2+SRT+L+W/2$ , where D is bump base diam-

eter, SRT is solder mask registration tolerance, W is trace line width, and L is the ligament separation between SRO and adjacent structures. In one embodiment, D is 100  $\mu\text{m}$ , SRT is 10  $\mu\text{m}$ , W is 30  $\mu\text{m}$ , and L is 60  $\mu\text{m}$ . The minimum escape pitch of trace lines 30-34 is  $100/2+10+60+30/2=135$   $\mu\text{m}$ . As the demand for high routing density increases, a smaller escape pitch is needed.

### SUMMARY OF THE INVENTION

A need exists to minimize escape pitch of trace lines for higher routing density. Accordingly, in one embodiment, the present invention is a method of making a semiconductor device comprising the steps of providing a semiconductor die having a die bump pad, providing a substrate having a conductive trace with an interconnect site, depositing a conductive bump material on the interconnect site or die bump pad, mounting the semiconductor die to the substrate so that the conductive bump material is disposed between the die bump pad and interconnect site, reflowing the conductive bump material without a solder mask around the die bump pad or interconnect site to form an interconnect structure between the semiconductor die and substrate, and depositing an encapsulant between the semiconductor die and substrate. The conductive bump material is self-confined within the die bump pad or interconnect site.

In another embodiment, the present invention is a method of making a semiconductor device comprising the steps of providing a first semiconductor structure having a first interconnect site, providing a second semiconductor structure having a second interconnect site, depositing a conductive bump material between the first and second interconnect sites, forming an interconnect structure from the conductive bump material to bond the first and second semiconductor structures without a solder mask around the first and second interconnect sites, depositing an encapsulant between the first and second semiconductor structures. The conductive bump material is self-confined within the first and second interconnect sites.

In another embodiment, the present invention is a method of making a semiconductor device comprising the steps of providing a first semiconductor structure having a first interconnect site, providing a second semiconductor structure having a second interconnect site, depositing a conductive bump material over a first interconnect site or second interconnect site, and forming an interconnect structure from the conductive bump material to bond the first and second semiconductor structures without a solder mask around the first and second interconnect sites.

In another embodiment, the present invention is a semiconductor device comprising a first semiconductor structure having a first interconnect site and second semiconductor structure having a second interconnect site. An interconnect structure is formed between the first and second semiconductor structures without a solder mask around the first and second interconnect sites. An encapsulant is deposited between the first and second semiconductor structures.

### BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 illustrates a cross-sectional view of a conventional interconnect formed between a semiconductor die and trace line on a substrate;

FIG. 2 illustrates a top view of the conventional interconnect formed over the trace line through a solder mask opening;

FIGS. 3a-3b illustrate conventional arrangement of trace lines between interconnects reflowed using a solder mask;

FIG. 4 illustrates a PCB with different types of packages mounted to its surface;

FIGS. 5a-5d illustrate further detail of the representative semiconductor packages mounted to the PCB;

FIGS. 6a-6b is a semiconductor device with interconnects reflowed on trace lines without a solder mask;

FIGS. 7a-7b show further detail of the bump pad along the trace line;

FIG. 8 shows a composite interconnect with non-fusible base and fusible cap;

FIGS. 9a-9b illustrate an alternate embodiment of the semiconductor device with interconnects reflowed on trace lines without a solder mask;

FIGS. 10a-10h illustrate various interconnect structures formed over a semiconductor die for bonding to conductive traces on a substrate;

FIGS. 11a-11g illustrate the semiconductor die and interconnect structure bonded to the conductive traces;

FIGS. 12a-12d illustrate the semiconductor die with a wedge-shaped interconnect structure bonded to the conductive traces;

FIGS. 13a-13d illustrate another embodiment of the semiconductor die and interconnect structure bonded to the conductive traces;

FIGS. 14a-14c illustrate stepped bump and stud bump interconnect structures bonded to the conductive traces;

FIGS. 15a-15b illustrate conductive traces with conductive vias;

FIGS. 16a-16c illustrate mold underfill between the semiconductor die and substrate;

FIG. 17 illustrates another mold underfill between the semiconductor die and substrate;

FIG. 18 illustrates the semiconductor die and substrate after mold underfill;

FIGS. 19a-19g illustrate various arrangements of the conductive traces with open solder registration;

FIGS. 20a-20b illustrate the open solder registration with patches between the conductive traces; and

FIG. 21 illustrates a POP with masking layer dam to restrain the encapsulant during mold underfill.

### DETAILED DESCRIPTION OF THE DRAWINGS

The present invention is described in one or more embodiments in the following description with reference to the figures, in which like numerals represent the same or similar elements. While the invention is described in terms of the best mode for achieving the invention's objectives, it will be appreciated by those skilled in the art that it is intended to cover alternatives, modifications, and equivalents as may be included within the spirit and scope of the invention as defined by the appended claims and their equivalents as supported by the following disclosure and drawings.

Semiconductor devices are generally manufactured using two complex manufacturing processes: front-end manufacturing and back-end manufacturing. Front-end manufacturing involves the formation of a plurality of die on the surface of a semiconductor wafer. Each die on the wafer contains active and passive electrical components, which are electrically connected to form functional electrical circuits. Active electrical components, such as transistors and diodes, have the ability to control the flow of electrical current. Passive electrical components, such as capacitors, inductors, resistors, and transformers, create a relationship between voltage and current necessary to perform electrical circuit functions.

Passive and active components are formed over the surface of the semiconductor wafer by a series of process steps including doping, deposition, photolithography, etching, and planarization. Doping introduces impurities into the semiconductor material by techniques such as ion implantation or thermal diffusion. The doping process modifies the electrical conductivity of semiconductor material in active devices, transforming the semiconductor material into an insulator, conductor, or dynamically changing the semiconductor material conductivity in response to an electric field or base current. Transistors contain regions of varying types and degrees of doping arranged as necessary to enable the transistor to promote or restrict the flow of electrical current upon the application of the electric field or base current.

Active and passive components are formed by layers of materials with different electrical properties. The layers can be formed by a variety of deposition techniques determined in part by the type of material being deposited. For example, thin film deposition can involve chemical vapor deposition (CVD), physical vapor deposition (PVD), electrolytic plating, and electroless plating processes. Each layer is generally patterned to form portions of active components, passive components, or electrical connections between components.

The layers can be patterned using photolithography, which involves the deposition of light sensitive material, e.g., photoresist, over the layer to be patterned. A pattern is transferred from a photomask to the photoresist using light. The portion of the photoresist pattern subjected to light is removed using a solvent, exposing portions of the underlying layer to be patterned. The remainder of the photoresist is removed, leaving behind a patterned layer. Alternatively, some types of materials are patterned by directly depositing the material into the areas or voids formed by a previous deposition/etch process using techniques such as electroless and electrolytic plating.

Depositing a thin film of material over an existing pattern can exaggerate the underlying pattern and create a non-uniformly flat surface. A uniformly flat surface is required to produce smaller and more densely packed active and passive components. Planarization can be used to remove material from the surface of the wafer and produce a uniformly flat surface. Planarization involves polishing the surface of the wafer with a polishing pad. An abrasive material and corrosive chemical are added to the surface of the wafer during polishing. The combined mechanical action of the abrasive and corrosive action of the chemical removes any irregular topography, resulting in a uniformly flat surface.

Back-end manufacturing refers to cutting or singulating the finished wafer into the individual die and then packaging the die for structural support and environmental isolation. To singulate the die, the wafer is scored and broken along non-functional regions of the wafer called saw streets or scribes. The wafer is singulated using a laser cutting tool or saw blade. After singulation, the individual die are mounted to a package substrate that includes pins or contact pads for interconnection with other system components. Contact pads formed over the semiconductor die are then connected to contact pads within the package. The electrical connections can be made with solder bumps, stud bumps, conductive paste, or wirebonds. An encapsulant or other molding material is deposited over the package to provide physical support and electrical isolation. The finished package is then inserted into an electrical system and the functionality of the semiconductor device is made available to the other system components.

FIG. 4 illustrates electronic device 50 having a chip carrier substrate or printed circuit board (PCB) 52 with a plurality of semiconductor packages mounted on its surface. Electronic

device 50 can have one type of semiconductor package, or multiple types of semiconductor packages, depending on the application. The different types of semiconductor packages are shown in FIG. 4 for purposes of illustration.

Electronic device 50 can be a stand-alone system that uses the semiconductor packages to perform one or more electrical functions. Alternatively, electronic device 50 can be a sub-component of a larger system. For example, electronic device 50 can be part of a cellular phone, personal digital assistant (PDA), digital video camera (DVC), or other electronic communication device. Alternatively, electronic device 50 can be a graphics card, network interface card, or other signal processing card that can be inserted into a computer. The semiconductor package can include microprocessors, memories, application specific integrated circuits (ASIC), logic circuits, analog circuits, RF circuits, discrete devices, or other semiconductor die or electrical components. The miniaturization and the weight reduction are essential for these products to be accepted by the market. The distance between semiconductor devices must be decreased to achieve higher density.

In FIG. 4, PCB 52 provides a general substrate for structural support and electrical interconnect of the semiconductor packages mounted on the PCB. Conductive signal traces 54 are formed over a surface or within layers of PCB 52 using evaporation, electrolytic plating, electroless plating, screen printing, or other suitable metal deposition process. Signal traces 54 provide for electrical communication between each of the semiconductor packages, mounted components, and other external system components. Traces 54 also provide power and ground connections to each of the semiconductor packages.

In some embodiments, a semiconductor device has two packaging levels. First level packaging is a technique for mechanically and electrically attaching the semiconductor die to an intermediate carrier. Second level packaging involves mechanically and electrically attaching the intermediate carrier to the PCB. In other embodiments, a semiconductor device may only have the first level packaging where the die is mechanically and electrically mounted directly to the PCB.

For the purpose of illustration, several types of first level packaging, including wire bond package 56 and flipchip 58, are shown on PCB 52. Additionally, several types of second level packaging, including ball grid array (BGA) 60, bump chip carrier (BCC) 62, dual in-line package (DIP) 64, land grid array (LGA) 66, multi-chip module (MCM) 68, quad flat non-leaded package (QFN) 70, and quad flat package 72, are shown mounted on PCB 52. Depending upon the system requirements, any combination of semiconductor packages, configured with any combination of first and second level packaging styles, as well as other electronic components, can be connected to PCB 52. In some embodiments, electronic device 50 includes a single attached semiconductor package, while other embodiments call for multiple interconnected packages. By combining one or more semiconductor packages over a single substrate, manufacturers can incorporate pre-made components into electronic devices and systems. Because the semiconductor packages include sophisticated functionality, electronic devices can be manufactured using cheaper components and a streamlined manufacturing process. The resulting devices are less likely to fail and less expensive to manufacture resulting in a lower cost for consumers.

FIGS. 5a-5d show exemplary semiconductor packages. FIG. 5a illustrates further detail of DIP 64 mounted on PCB 52. Semiconductor die 74 includes an active region containing analog or digital circuits implemented as active devices,

passive devices, conductive layers, and dielectric layers formed within the die and are electrically interconnected according to the electrical design of the die. For example, the circuit can include one or more transistors, diodes, inductors, capacitors, resistors, and other circuit elements formed within the active region of semiconductor die **74**. Contact pads **76** are one or more layers of conductive material, such as aluminum (Al), copper (Cu), tin (Sn), nickel (Ni), gold (Au), or silver (Ag), and are electrically connected to the circuit elements formed within semiconductor die **74**. During assembly of DIP **64**, semiconductor die **74** is mounted to an intermediate carrier **78** using a gold-silicon eutectic layer or adhesive material such as thermal epoxy or epoxy resin. The package body includes an insulative packaging material such as polymer or ceramic. Conductor leads **80** and bond wires **82** provide electrical interconnect between semiconductor die **74** and PCB **52**. Encapsulant **84** is deposited over the package for environmental protection by preventing moisture and particles from entering the package and contaminating die **74** or bond wires **82**.

FIG. **5b** illustrates further detail of BCC **62** mounted on PCB **52**. Semiconductor die **88** is mounted over carrier **90** using an underfill or epoxy-resin adhesive material **92**. Bond wires **94** provide first level packaging interconnect between contact pads **96** and **98**. Molding compound or encapsulant **100** is deposited over semiconductor die **88** and bond wires **94** to provide physical support and electrical isolation for the device. Contact pads **102** are formed over a surface of PCB **52** using a suitable metal deposition process such as electrolytic plating or electroless plating to prevent oxidation. Contact pads **102** are electrically connected to one or more conductive signal traces **54** in PCB **52**. Bumps **104** are formed between contact pads **98** of BCC **62** and contact pads **102** of PCB **52**.

In FIG. **5c**, semiconductor die **58** is mounted face down to intermediate carrier **106** with a flipchip style first level packaging. Active region **108** of semiconductor die **58** contains analog or digital circuits implemented as active devices, passive devices, conductive layers, and dielectric layers formed according to the electrical design of the die. For example, the circuit can include one or more transistors, diodes, inductors, capacitors, resistors, and other circuit elements within active region **108**. Semiconductor die **58** is electrically and mechanically connected to carrier **106** through bumps **110**.

BGA **60** is electrically and mechanically connected to PCB **52** with a BGA style second level packaging using bumps **112**. Semiconductor die **58** is electrically connected to conductive signal traces **54** in PCB **52** through bumps **110**, signal lines **114**, and bumps **112**. A molding compound or encapsulant **116** is deposited over semiconductor die **58** and carrier **106** to provide physical support and electrical isolation for the device. The flipchip semiconductor device provides a short electrical conduction path from the active devices on semiconductor die **58** to conduction tracks on PCB **52** in order to reduce signal propagation distance, lower capacitance, and improve overall circuit performance. In another embodiment, the semiconductor die **58** can be mechanically and electrically connected directly to PCB **52** using flipchip style first level packaging without intermediate carrier **106**.

In another embodiment, active area **108** of semiconductor die **58** is directly mounted facedown to PCB **115**, i.e., without an intermediate carrier, as shown in FIG. **5d**. Bump pads **111** are formed on active area **108** using an evaporation, electrolytic plating, electroless plating, screen printing, or other suitable metal deposition process. Bump pads **111** connect to the active and passive circuits by conduction tracks in active area **108**. Bump pads **111** can be Al, Sn, Ni, Au, Ag, or Cu. An electrically conductive bump material is deposited over bump

pads **111** using an evaporation, electrolytic plating, electroless plating, ball drop, or screen printing process. The bump material can be Al, Sn, Ni, Au, Ag, lead (Pb), Bi, Cu, solder, and combinations thereof, with an optional flux material. For example, the bump material can be eutectic Sn/Pb, high-lead solder, or lead-free solder. The bump material is bonded to die bump pads **160** using a suitable attachment or bonding process. In one embodiment, the bump material is reflowed by heating the material above its melting point to form spherical balls or bumps **117**. In some applications, bumps **117** are reflowed a second time to improve electrical contact to bump pads **111**. The flipchip semiconductor device provides a short electrical conduction path from the active devices on semiconductor die **58** to conduction tracks on PCB **115** in order to reduce signal propagation, lower capacitance, and achieve overall better circuit performance.

FIGS. **6a** and **6b** illustrate a top view and cross-sectional view of a portion of flipchip type semiconductor die **120** with die bump pad **122**. Trace line **124** is a straight conductor with integrated bump pad **126** formed on substrate or PCB **130**. FIGS. **7a** and **7b** show further detail of substrate bump pad **126** along trace line **124**. The substrate bump pad **126** can be rounded as shown in FIG. **7a**, or rectangular as shown in FIG. **7b**. The sides of substrate bump pad **126** can be co-linear with trace line **124**.

An electrically conductive bump material is deposited over die bump pad **122** or substrate bump pad **126** using an evaporation, electrolytic plating, electroless plating, ball drop, or screen printing process. The bump material can be Al, Sn, Ni, Au, Ag, Pb, Bi, Cu, solder, and combinations thereof, with an optional flux solution. For example, the bump material can be eutectic Sn/Pb, high-lead solder, or lead-free solder. The bump material is bonded to die bump pad **122** and substrate bump pad **126** using a suitable attachment or bonding process. In one embodiment, the bump material is reflowed by heating the material above its melting point to form interconnect **132**. In some applications, interconnect **132** is reflowed a second time to improve electrical contact between die bump pad **122** and substrate bump pad **126**. The bump material around the narrow substrate bump pad **126** maintains die placement during reflow. Although interconnect **132** is shown connected to trace line **124** as a bump-on-lead (BOL), the interconnect can also be formed over a bump pad on substrate **130** having an area on the same order or greater than die bump pad **122**. An optional underfill material **138** is deposited between semiconductor die **120** and substrate **130**.

In high routing density applications, it is desirable to minimize escape pitch of trace lines **124**. The escape pitch between trace lines **124** can be reduced by eliminating the solder mask for reflow containment, i.e., by reflowing the bump material without a solder mask. Solder mask **140** can be formed over a portion of substrate **130**. However, solder mask **140** is not formed over substrate bump pad **126** of trace line **124** for reflow containment. That is, the portion of trace line **124** designed to mate with the bump material is devoid of any SRO of solder mask **140**. Since no SRO is formed around die bump pad **122** or substrate bump pad **126**, trace lines **124** can be formed with a finer pitch, i.e., trace lines **124** can be disposed closer together or to nearby structures. Without solder mask **140**, the pitch between trace lines **124** is given as  $P=D+PLT+W/2$ , wherein  $D$  is the base diameter of interconnect **132**,  $PLT$  is die placement tolerance, and  $W$  is the width of the trace line **124**. In one embodiment, given a bump base diameter of 100  $\mu\text{m}$ ,  $PLT$  of 10  $\mu\text{m}$ , and trace line width of 30  $\mu\text{m}$ , the minimum escape pitch of trace line **124** is 125  $\mu\text{m}$ . The solder mask-less bump formation eliminates the need to account for the ligament spacing of solder mask material

between adjacent openings, SRT, and minimum resolvable SRO, as found in the prior art.

When the bump material is reflowed without a solder mask to metallurgically and electrically connect die bump pad 122 to substrate bump pad 126, the wetting and surface tension causes the bump material to maintain self-confinement and be retained within the space between die bump pad 122 and substrate bump pad 126 and portion of substrate 130 immediately adjacent to trace line 124 substantially within the footprint of the bump pads.

To achieve the desired self-confinement property, the bump material can be immersed in a flux solution prior to placement on die bump pad 122 or substrate bump pad 126 to selectively render the region contacted by the bump material more wettable than the surrounding area of trace line 124. The molten bump material remains confined substantially within the area defined by the bump pads due to the wettable properties of the flux solution. The bump material does not run-out to the less wettable areas. A thin oxide layer or other insulating layer can be formed over areas where bump material is not intended to make the area less wettable. Hence, solder mask 140 is not needed around die bump pad 122 or substrate bump pad 126.

In another embodiment, a composite interconnect 144 is formed between die bump pad 122 and substrate bump pad 126 to achieve the desired self-confinement of the bump material. Composite interconnect 144 includes a non-fusible base 146 made of Cu, Au, Sn, Ni, and Pb, and a fusible cap 148 made of solder, Sn, or indium, as shown in FIG. 8. The volume of fusible bump material in relation to the non-fusible base material is selected to ensure self-confinement by virtue of surface tension forces. During reflow, the fusible base material is self-confined around the non-fusible base material. The fusible bump material around the non-fusible base also maintains die placement during reflow. In general, the height of composite interconnect 144 is the same or less than the diameter of the bump. In some cases, the height of composite interconnect 144 is greater than the diameter of the interconnect. In one embodiment, given a bump base diameter of 100  $\mu\text{m}$ , the non-fusible base 146 is about 45  $\mu\text{m}$  in height and the fusible cap 148 is about 35  $\mu\text{m}$  in height. The molten bump material remains confined substantially within the area defined by the bump pads because the volume of bump material deposited to form composite bump 144, including non-fusible base 146 and fusible cap 148, is selected so that the resulting surface tension is sufficient to retain the bump material substantially within the footprint of the bump pads and prevent run-out to unintended adjacent or nearby areas. Hence, solder mask 140 is not needed around die bump pad 122 or substrate bump pad 126, which reduces trace line pitch and increases routing density.

FIGS. 9a and 9b illustrate a top view and cross-sectional view of another embodiment with flipchip type semiconductor die 150 having die bump pad 152. Trace line 154 is a straight conductor with integrated bump pad 156 formed on substrate or PCB 160, similar to FIGS. 7a and 7b. In this embodiment, bump pads 156 are arranged in multiple or offset rows. Accordingly, alternate trace lines 154 include an elbow for routing to bump pads 156.

An electrically conductive bump material is deposited over die bump pad 152 or substrate bump pad 156 using an evaporation, electrolytic plating, electroless plating, ball drop, or screen printing process. The bump material can be Al, Sn, Ni, Au, Ag, Pb, Bi, Cu, solder, and combinations thereof, with an optional flux solution. For example, the bump material can be eutectic Sn/Pb, high-lead solder, or lead-free solder. The bump material is bonded to die bump pad 152 and substrate bump pad 156 using a suitable attachment or bonding pro-

cess. In one embodiment, the bump material is reflowed by heating the material above its melting point to form bump or interconnect 162. In some applications, interconnect 162 is reflowed a second time to improve electrical contact between die bump pad 152 and substrate bump pad 156. The bump material around the narrow substrate bump pad 156 maintains die placement during reflow. Although interconnect 162 is shown connected to trace line 154 as BOL, the bump material can also be reflowed over a bump pad on substrate 160 having an area on the same order or greater than die bump pad 152. An optional underfill material 168 is deposited between semiconductor die 150 and substrate 160.

In high routing density applications, it is desirable to minimize escape pitch. In order to reduce the pitch between trace lines 154, the bump material is reflowed without a solder mask. The escape pitch between trace lines 154 can be reduced by eliminating the solder mask for solder reflow containment, i.e., by reflowing the bump material without a solder mask. Solder mask 170 can be formed over a portion of substrate 160. However, solder mask 170 is not formed over substrate bump pad 156 of trace line 154 for solder reflow containment. That is, the portion of trace line 154 designed to mate with the bump material is devoid of an SRO of solder mask 170. Since no SRO is formed around die bump pad 152 or substrate bump pad 156, trace lines 154 can be formed with a finer pitch, i.e., trace lines 154 can be disposed closer to adjacent structures.

Without solder mask 170, the pitch between trace lines 154 is given as  $P=D/2+PLT+W/2$ , wherein D is the base diameter of bump 162, PLT is die placement tolerance, and W is the width of the trace line 154. In one embodiment, given a bump diameter of 100  $\mu\text{m}$ , PLT of 10  $\mu\text{m}$ , and trace line width of 30  $\mu\text{m}$ , the minimum escape pitch of trace line 154 is 75  $\mu\text{m}$ . The solder mask-less bump formation eliminates the need to account for the ligament spacing of solder mask material between adjacent openings, SRT, and minimum resolvable SRO, as found in the prior art.

When the bump material is reflowed without a solder mask to metallurgically and electrically connect die bump pad 152 of semiconductor die 150 to substrate bump pad 156 of trace line 154, the wetting and surface tension causes the bump to maintain self-confinement and be retained within the space between die bump pad 152 and substrate bump pad 156 and portion of substrate 160 immediately adjacent to trace line 154 substantially within the footprint of the bump pads.

To achieve the desired self-confinement property, the bump material can be immersed in a flux solution prior to placement on die bump pad 152 or substrate bump pad 156 to selectively render the region contacted by the bump material more wettable than the surrounding area of trace line 154. The molten bump material remains confined substantially within the area defined by the bump pads due to the wettable properties of the flux solution. The bump material does not run-out to the less wettable areas. A thin oxide layer or other insulating layer can be formed over areas where bump material is not intended to make the area less wettable. Hence, solder mask 170 is not needed around die bump pad 152 or substrate bump pad 156.

In another embodiment, a composite interconnect is formed between die bump pad 152 and substrate bump pad 156 to achieve the desired self-confinement of the bump material. The composite interconnect includes a non-fusible base made of Cu, Au, Sn, Ni, or Pb, and a fusible cap made of solder, Sn, or indium, similar to FIG. 8. The height or volume of fusible bump material in relation to the non-fusible base material is selected to ensure self-confinement by virtue of surface tension forces. During reflow, the fusible base material is self-confined around the non-fusible base material. The

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fusible bump material around the non-fusible base also maintains die placement during reflow. In general the height of the composite interconnect is the same or less than the diameter of the bump. In some cases, the height of the composite interconnect is greater than the diameter of the interconnect. In one embodiment, given a bump base diameter of 100  $\mu\text{m}$ , the non-fusible base is about 45  $\mu\text{m}$  in height and the fusible cap is about 35  $\mu\text{m}$  in height. The molten bump material remains confined substantially within the area defined by the bump pads because the volume of bump material deposited to form the composite bump, including non-fusible base and fusible cap, is selected so that the resulting surface tension is sufficient to retain the bump material substantially within the footprint of the bump pads and prevent run-out to unintended adjacent or nearby areas. Hence, solder mask 170 is not needed around die bump pad 152 or substrate bump pad 156, which reduces trace line pitch and increases routing density.

FIGS. 10-15 describe other embodiments with various interconnect structures applicable to the no SRO interconnect structure, as described in FIGS. 6-9. FIG. 10a shows a semiconductor wafer 220 with a base substrate material 222, such as silicon, germanium, gallium arsenide, indium phosphide, or silicon carbide, for structural support. A plurality of semiconductor die or components 224 is formed on wafer 220 separated by saw streets 226 as described above.

FIG. 10b shows a cross-sectional view of a portion of semiconductor wafer 220. Each semiconductor die 224 has a back surface 228 and active surface 230 containing analog or digital circuits implemented as active devices, passive devices, conductive layers, and dielectric layers formed within the die and electrically interconnected according to the electrical design and function of the die. For example, the circuit can include one or more transistors, diodes, and other circuit elements formed within active surface 230 to implement analog circuits or digital circuits, such as digital signal processor (DSP), ASIC, memory, or other signal processing circuit. Semiconductor die 224 can also contain integrated passive devices (IPDs), such as inductors, capacitors, and resistors, for RF signal processing. In one embodiment, semiconductor die 224 is a flipchip type semiconductor die.

An electrically conductive layer 232 is formed over active surface 230 using PVD, CVD, electrolytic plating, electroless plating process, or other suitable metal deposition process. Conductive layer 232 can be one or more layers of Al, Cu, Sn, Ni, Au, Ag, or other suitable electrically conductive material. Conductive layer 232 operates as contact pads or die bumps pads electrically connected to the circuits on active surface 230.

FIG. 10c shows a portion of semiconductor wafer 220 with an interconnect structure formed over contact pads 232. An electrically conductive bump material 234 is deposited over contact pads 232 using an evaporation, electrolytic plating, electroless plating, ball drop, or screen printing process. Bump material 234 can be Al, Sn, Ni, Au, Ag, Pb, Bi, Cu, solder, and combinations thereof, with an optional flux solution. For example, bump material 234 can be eutectic Sn/Pb, high-lead solder, or lead-free solder. Bump material 234 is generally compliant and undergoes plastic deformation greater than about 25  $\mu\text{m}$  under a force equivalent to a vertical load of about 200 grams. Bump material 234 is bonded to contact pad 232 using a suitable attachment or bonding process. For example, bump material 234 can be compression bonded to contact pad 232. Bump material 234 can also be reflowed by heating the material above its melting point to form spherical balls or bumps 236, as shown in FIG. 10d. In some applications, bumps 236 are reflowed a second time to improve electrical connection to contact pad 232. Bumps 236

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represent one type of interconnect structure that can be formed over contact pad 232. The interconnect structure can also use stud bump, micro bump, or other electrical interconnect.

FIG. 10e shows another embodiment of the interconnect structure formed over contact pads 232 as composite bumps 238 including a non-fusible or non-collapsible portion 240 and fusible or collapsible portion 242. The fusible or collapsible and non-fusible or non-collapsible attributes are defined for bumps 238 with respect to reflow conditions. The non-fusible portion 240 can be Au, Cu, Ni, high-lead solder, or lead-tin alloy. The fusible portion 242 can be Sn, lead-free alloy, Sn—Ag alloy, Sn—Ag—Cu alloy, Sn—Ag—indium (In) alloy, eutectic solder, tin alloys with Ag, Cu, or Pb, or other relatively low temperature melt solder. In one embodiment, given a contact pad 232 width or diameter of 100  $\mu\text{m}$ , the non-fusible portion 240 is about 45  $\mu\text{m}$  in height and fusible portion 242 is about 35  $\mu\text{m}$  in height.

FIG. 10f shows another embodiment of the interconnect structure formed over contact pads 232 as bump 244 over conductive pillar 246. Bump 244 is fusible or collapsible and conductive pillar 246 is non-fusible or non-collapsible. The fusible or collapsible and non-fusible or non-collapsible attributes are defined with respect to reflow conditions. Bump 244 can be Sn, lead-free alloy, Sn—Ag alloy, Sn—Ag—Cu alloy, Sn—Ag—In alloy, eutectic solder, tin alloys with Ag, Cu, or Pb, or other relatively low temperature melt solder. Conductive pillar 246 can be Au, Cu, Ni, high-lead solder, or lead-tin alloy. In one embodiment, conductive pillar 246 is a Cu pillar and bump 244 is a solder cap. Given a contact pad 232 width or diameter of 100  $\mu\text{m}$ , conductive pillar 246 is about 45  $\mu\text{m}$  in height and bump 244 is about 35  $\mu\text{m}$  in height.

FIG. 10g shows another embodiment of the interconnect structure formed over contact pads 232 as bump material 248 with asperities 250. Bump material 248 is soft and deformable under reflow conditions with a low yield strength and high elongation to failure, similar to bump material 234. Asperities 250 are formed with a plated surface finish and are shown exaggerated in the figures for purposes of illustration. The scale of asperities 250 is generally in the order about 1-25  $\mu\text{m}$ . The asperities can also be formed on bump 236, composite bump 238, and bump 244.

In FIG. 10h, semiconductor wafer 220 is singulated through saw street 226 using a saw blade or laser cutting tool 252 into individual semiconductor die 224.

FIG. 11a shows a substrate or PCB 254 with conductive trace 256. Substrate 254 can be a single-sided FR5 laminate or 2-sided BT-resin laminate. Semiconductor die 224 is positioned so that bump material 234 is aligned with an interconnect site on conductive trace 256, see FIGS. 19a-19g. Alternatively, bump material 234 can be aligned with a conductive pad or other interconnect site formed on substrate 254. Bump material 234 is wider than conductive trace 256. In one embodiment, bump material 234 has a width of less than 100  $\mu\text{m}$  and conductive trace or pad 256 has a width of 35  $\mu\text{m}$  for a bump pitch of 150  $\mu\text{m}$ . Conductive traces 256 is applicable to the no SRO interconnect structure, as described in FIGS. 6-9.

A pressure or force F is applied to back surface 228 of semiconductor die 224 to press bump material 234 onto conductive trace 256. The force F can be applied with an elevated temperature. Due to the compliant nature of bump material 234, the bump material deforms or extrudes around the top surface and side surface of conductive trace 256, referred to as BOL. In particular, the application of pressure causes bump material 234 to undergo a plastic deformation greater than about 25  $\mu\text{m}$  under force F equivalent to a vertical load of



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about 200 grams and cover the top surface and side surface of the conductive trace, as shown in FIG. 11*b*. Bump material 234 can also be metallurgically connected to conductive trace 256 by bringing the bump material in physical contact with the conductive trace and then reflowing the bump material under a reflow temperature.

By making conductive trace 256 narrower than bump material 234, the conductive trace pitch can be reduced to increase routing density and I/O count. The narrower conductive trace 256 reduces the force *F* needed to deform bump material 234 around the conductive trace. For example, the requisite force *F* may be 30-50% of the force needed to deform bump material against a conductive trace or pad that is wider than the bump material. The lower compressive force *F* is useful for fine pitch interconnect and small die to maintain coplanarity with a specified tolerance and achieve uniform z-direction deformation and high reliability interconnect union. In addition, deforming bump material 234 around conductive trace 256 mechanically locks the bump to the trace to prevent die shifting or die floating during reflow.

FIG. 11*c* shows bump 236 formed over contact pad 232 of semiconductor die 224. Semiconductor die 224 is positioned so that bump 236 is aligned with an interconnect site on conductive trace 256. Alternatively, bump 236 can be aligned with a conductive pad or other interconnect site formed on substrate 254. Bump 236 is wider than conductive trace 256. Conductive traces 256 is applicable to the no SRO interconnect structure, as described in FIGS. 6-9.

A pressure or force *F* is applied to back surface 228 of semiconductor die 224 to press bump 236 onto conductive trace 256. The force *F* can be applied with an elevated temperature. Due to the compliant nature of bump 236, the bump deforms or extrudes around the top surface and side surface of conductive trace 256. In particular, the application of pressure causes bump material 236 to undergo a plastic deformation and cover the top surface and side surface of conductive trace 256. Bump 236 can also be metallurgically connected to conductive trace 256 by bringing the bump in physical contact with the conductive trace under reflow temperature.

By making conductive trace 256 narrower than bump 236, the conductive trace pitch can be reduced to increase routing density and I/O count. The narrower conductive trace 256 reduces the force *F* needed to deform bump 236 around the conductive trace. For example, the requisite force *F* may be 30-50% of the force needed to deform a bump against a conductive trace or pad that is wider than the bump. The lower compressive force *F* is useful for fine pitch interconnect and small die to maintain coplanarity within a specified tolerance and achieve uniform z-direction deformation and high reliability interconnect union. In addition, deforming bump 236 around conductive trace 256 mechanically locks the bump to the trace to prevent die shifting or die floating during reflow.

FIG. 11*d* shows composite bump 238 formed over contact pad 232 of semiconductor die 224. Semiconductor die 224 is positioned so that composite bump 238 is aligned with an interconnect site on conductive trace 256. Alternatively, composite bump 238 can be aligned with a conductive pad or other interconnect site formed on substrate 254. Composite bump 238 is wider than conductive trace 256. Conductive traces 256 is applicable to the no SRO interconnect structure, as described in FIGS. 6-9.

A pressure or force *F* is applied to back surface 228 of semiconductor die 224 to press fusible portion 242 onto conductive trace 256. The force *F* can be applied with an elevated temperature. Due to the compliant nature of fusible portion 242, the fusible portion deforms or extrudes around the top surface and side surface of conductive trace 256. In particular,

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the application of pressure causes fusible portion 242 to undergo a plastic deformation and cover the top surface and side surface of conductive trace 256. Composite bump 238 can also be metallurgically connected to conductive trace 256 by bringing fusible portion 242 in physical contact with the conductive trace under reflow temperature. The non-fusible portion 240 does not melt or deform during the application of pressure or temperature and retains its height and shape as a vertical standoff between semiconductor die 224 and substrate 254. The additional displacement between semiconductor die 224 and substrate 254 provides greater coplanarity tolerance between the mating surfaces.

During a reflow process, a large number (e.g., thousands) of composite bumps 238 on semiconductor die 224 are attached to interconnect sites on conductive trace 256 of substrate 254. Some of the bumps 238 may fail to properly connect to conductive trace 256, particularly if die 224 is warped. Recall that composite bump 238 is wider than conductive trace 256. With a proper force applied, the fusible portion 242 deforms or extrudes around the top surface and side surface of conductive trace 256 and mechanically locks composite bump 238 to the conductive trace. The mechanical interlock is formed by nature of the fusible portion 242 being softer and more compliant than conductive trace 256 and therefore deforming over the top surface and around the side surface of the conductive trace for greater contact surface area. The mechanical interlock between composite bump 238 and conductive trace 256 holds the bump to the conductive trace during reflow, i.e., the bump and conductive trace do not lose contact. Accordingly, composite bump 238 mating to conductive trace 256 reduces bump interconnect failures.

FIG. 11*e* shows conductive pillar 246 and bump 244 formed over contact pad 232 of semiconductor die 224. Semiconductor die 224 is positioned so that bump 244 is aligned with an interconnect site on conductive trace 256.

Alternatively, bump 244 can be aligned with a conductive pad or other interconnect site formed on substrate 254. Bump 244 is wider than conductive trace 256. Conductive traces 256 is applicable to the no SRO interconnect structure, as described in FIGS. 6-9.

A pressure or force *F* is applied to back surface 228 of semiconductor die 224 to press bump 244 onto conductive trace 256. The force *F* can be applied with an elevated temperature. Due to the compliant nature of bump 244, the bump deforms or extrudes around the top surface and side surface of conductive trace 256. In particular, the application of pressure causes bump 244 to undergo a plastic deformation and cover the top surface and side surface of conductive trace 256. Conductive pillar 246 and bump 244 can also be metallurgically connected to conductive trace 256 by bringing the bump in physical contact with the conductive trace under reflow temperature. Conductive pillar 246 does not melt or deform during the application of pressure or temperature and retains its height and shape as a vertical standoff between semiconductor die 224 and substrate 254. The additional displacement between semiconductor die 224 and substrate 254 provides greater coplanarity tolerance between the mating surfaces. The wider bump 244 and narrower conductive trace 256 have similar low requisite compressive force and mechanical locking features and advantages described above for bump material 234 and bump 236.

FIG. 11*f* shows bump material 248 with asperities 250 formed over contact pad 232 of semiconductor die 224. Semiconductor die 224 is positioned so that bump material 248 is aligned with an interconnect site on conductive trace 256. Alternatively, bump material 248 can be aligned with a conductive pad or other interconnect site formed on substrate

254. Bump material 248 is wider than conductive trace 256. A pressure or force F is applied to back surface 228 of semiconductor die 224 to press bump material 248 onto conductive trace 256. The force F can be applied with an elevated temperature. Due to the compliant nature of bump material 248, the bump deforms or extrudes around the top surface and side surface of conductive trace 256. In particular, the application of pressure causes bump material 248 to undergo a plastic deformation and cover the top surface and side surface of conductive trace 256. In addition, asperities 250 are metallurgically connected to conductive trace 256. Asperities 250 are sized on the order about 1-25  $\mu\text{m}$ .

FIG. 11g shows a substrate or PCB 258 with trapezoidal conductive trace 260 having angled or sloped sides. Bump material 261 is formed over contact pad 232 of semiconductor die 224. Semiconductor die 224 is positioned so that bump material 261 is aligned with an interconnect site on conductive trace 260. Alternatively, bump material 261 can be aligned with a conductive pad or other interconnect site formed on substrate 258. Bump material 261 is wider than conductive trace 260. Conductive traces 260 is applicable to the no SRO interconnect structure, as described in FIGS. 6-9.

A pressure or force F is applied to back surface 228 of semiconductor die 224 to press bump material 261 onto conductive trace 260. The force F can be applied with an elevated temperature. Due to the compliant nature of bump material 261, the bump material deforms or extrudes around the top surface and side surface of conductive trace 260. In particular, the application of pressure causes bump material 261 to undergo a plastic deformation under force F to cover the top surface and the angled side surface of conductive trace 260. Bump material 261 can also be metallurgically connected to conductive trace 260 by bringing the bump material in physical contact with the conductive trace and then reflowing the bump material under a reflow temperature.

FIGS. 12a-12d show a BOL embodiment of semiconductor die 224 and elongated composite bump 262 having a non-fusible or non-collapsible portion 264 and fusible or collapsible portion 266. The non-fusible portion 264 can be Au, Cu, Ni, high-lead solder, or lead-tin alloy. The fusible portion 266 can be Sn, lead-free alloy, Sn—Ag alloy, Sn—Ag—Cu alloy, Sn—Ag—In alloy, eutectic solder, tin alloys with Ag, Cu, or Pb, or other relatively low temperature melt solder. The non-fusible portion 264 makes up a larger part of composite bump 262 than the fusible portion 266. The non-fusible portion 264 is fixed to contact pad 232 of semiconductor die 224.

Semiconductor die 224 is positioned so that composite bump 262 is aligned with an interconnect site on conductive trace 268 formed on substrate 270, as shown in FIG. 12a. Composite bump 262 is tapered along conductive trace 268, i.e., the composite bump has a wedge shape, longer along a length of conductive trace 268 and narrower across the conductive trace. The tapered aspect of composite bump 262 occurs along the length of conductive trace 268. The view in FIG. 12a shows the shorter aspect or narrowing taper collinear with conductive trace 268. The view in FIG. 12b, normal to FIG. 12a, shows the longer aspect of the wedge-shaped composite bump 262. The shorter aspect of composite bump 262 is wider than conductive trace 268. The fusible portion 266 collapses around conductive trace 268 upon application of pressure and/or reflow with heat, as shown in FIGS. 12c and 12d. The non-fusible portion 264 does not melt or deform during reflow and retains its form and shape. The non-fusible portion 264 can be dimensioned to provide a standoff distance between semiconductor die 224 and substrate 270. A finish

such as Cu OSP can be applied to substrate 270. Conductive traces 268 is applicable to the no SRO interconnect structure, as described in FIGS. 6-9.

During a reflow process, a large number (e.g., thousands) of composite bumps 262 on semiconductor die 224 are attached to interconnect sites on conductive trace 268 of substrate 270. Some of the bumps 262 may fail to properly connect to conductive trace 268, particularly if semiconductor die 224 is warped. Recall that composite bump 262 is wider than conductive trace 268. With a proper force applied, the fusible portion 266 deforms or extrudes around the top surface and side surface of conductive trace 268 and mechanically locks composite bump 262 to the conductive trace. The mechanical interlock is formed by nature of the fusible portion 266 being softer and more compliant than conductive trace 268 and therefore deforming around the top surface and side surface of the conductive trace for greater contact area. The wedge-shape of composite bump 262 increases contact area between the bump and conductive trace, e.g., along the longer aspect of FIGS. 12b and 12d, without sacrificing pitch along the shorter aspect of FIGS. 12a and 12c. The mechanical interlock between composite bump 262 and conductive trace 268 holds the bump to the conductive trace during reflow, i.e., the bump and conductive trace do not lose contact. Accordingly, composite bump 262 mating to conductive trace 268 reduces bump interconnect failures.

FIGS. 13a-13d show a BOL embodiment of semiconductor die 224 with bump material 274 formed over contact pads 232, similar to FIG. 10c. In FIG. 13a, bump material 274 is generally compliant and undergoes plastic deformation greater than about 25  $\mu\text{m}$  under a force equivalent to a vertical load of about 200 grams. Bump material 274 is wider than conductive trace 276 on substrate 278. A plurality of asperities 280 is formed on conductive trace 276 with a height on the order about 1-25  $\mu\text{m}$ .

Semiconductor die 224 is positioned so that bump material 274 is aligned with an interconnect site on conductive trace 276. Alternatively, bump material 274 can be aligned with a conductive pad or other interconnect site formed on substrate 278. A pressure or force F is applied to back surface 228 of semiconductor die 224 to press bump material 274 onto conductive trace 276 and asperities 280, as shown in FIG. 13b. The force F can be applied with an elevated temperature. Due to the compliant nature of bump material 274, the bump material deforms or extrudes around the top surface and side surface of conductive trace 276 and asperities 280. In particular, the application of pressure causes bump material 274 to undergo a plastic deformation and cover the top surface and side surface of conductive trace 276 and asperities 280. The plastic flow of bump material 274 creates macroscopic mechanical interlocking points between the bump material and the top surface and side surface of conductive trace 276 and asperities 280. The plastic flow of bump material 274 occurs around the top surface and side surface of conductive trace 276 and asperities 280, but does not extend excessively onto substrate 278, which could cause electrical shorting and other defects. The mechanical interlock between the bump material and the top surface and side surface of conductive trace 276 and asperities 280 provides a robust connection with greater contact area between the respective surfaces, without significantly increasing the bonding force. The mechanical interlock between the bump material and the top surface and side surface of conductive trace 276 and asperities 280 also reduces lateral die shifting during subsequent manufacturing processes, such as encapsulation.

FIG. 13c shows another BOL embodiment with bump material 274 narrower than conductive trace 276. A pressure

or force *F* is applied to back surface **228** of semiconductor die **224** to press bump material **274** onto conductive trace **276** and asperities **280**. The force *F* can be applied with an elevated temperature. Due to the compliant nature of bump material **274**, the bump material deforms or extrudes over the top surface of conductive trace **276** and asperities **280**. In particular, the application of pressure causes bump material **274** to undergo a plastic deformation and cover the top surface of conductive trace **276** and asperities **280**. The plastic flow of bump material **274** creates macroscopic mechanical interlocking points between the bump material and the top surface of conductive trace **276** and asperities **280**. The mechanical interlock between the bump material and the top surface of conductive trace **276** and asperities **280** provides a robust connection with greater contact area between the respective surfaces, without significantly increasing the bonding force. The mechanical interlock between the bump material and the top surface of conductive trace **276** and asperities **280** also reduces lateral die shifting during subsequent manufacturing processes, such as encapsulation.

FIG. **13d** shows another BOL embodiment with bump material **274** formed over an edge of conductive trace **276**, i.e., part of the bump material is over the conductive trace and part of the bump material is not over the conductive trace. A pressure or force *F* is applied to back surface **228** of semiconductor die **224** to press bump material **274** onto conductive trace **276** and asperities **280**. The force *F* can be applied with an elevated temperature. Due to the compliant nature of bump material **274**, the bump material deforms or extrudes over the top surface and side surface of conductive trace **276** and asperities **280**. In particular, the application of pressure causes bump material **274** to undergo a plastic deformation and cover the top surface and side surface of conductive trace **276** and asperities **280**. The plastic flow of bump material **274** creates macroscopic mechanical interlocking between the bump material and the top surface and side surface of conductive trace **276** and asperities **280**. The mechanical interlock between the bump material and the top surface and side surface of conductive trace **276** and asperities **280** provides a robust connection with greater contact area between the respective surfaces, without significantly increasing the bonding force. The mechanical interlock between the bump material and the top surface and side surface of conductive trace **276** and asperities **280** also reduces lateral die shifting during subsequent manufacturing processes, such as encapsulation.

FIGS. **14a-14c** show a BOL embodiment of semiconductor die **224** with bump material **284** formed over contact pads **232**, similar to FIG. **10c**. A tip **286** extends from the body of bump material **284** as a stepped bump with tip **286** narrower than the body of bump material **284**, as shown in FIG. **14a**. Semiconductor die **224** is positioned so that bump material **284** is aligned with an interconnect site on conductive trace **288** on substrate **290**. More specifically, tip **286** is centered over an interconnect site on conductive trace **288**. Alternatively, bump material **284** and tip **286** can be aligned with a conductive pad or other interconnect site formed on substrate **290**. Bump material **284** is wider than conductive trace **288** on substrate **290**.

Conductive trace **288** is generally compliant and undergoes plastic deformation greater than about 25  $\mu\text{m}$  under a force equivalent to a vertical load of about 200 grams. A pressure or force *F* is applied to back surface **228** of semiconductor die **224** to press tip **286** onto conductive trace **288**. The force *F* can be applied with an elevated temperature. Due to the compliant nature of conductive trace **288**, the conductive trace deforms around tip **286**, as shown in FIG. **14b**. In par-

ticular, the application of pressure causes conductive trace **288** to undergo a plastic deformation and cover the top surface and side surface of tip **286**.

FIG. **14c** shows another BOL embodiment with rounded bump material **294** formed over contact pads **232**. A tip **296** extends from the body of bump material **294** to form a stud bump with the tip narrower than the body of bump material **294**. Semiconductor die **224** is positioned so that bump material **294** is aligned with an interconnect site on conductive trace **298** on substrate **300**. More specifically, tip **296** is centered over an interconnect site on conductive trace **298**. Alternatively, bump material **294** and tip **296** can be aligned with a conductive pad or other interconnect site formed on substrate **300**. Bump material **294** is wider than conductive trace **298** on substrate **300**.

Conductive trace **298** is generally compliant and undergoes plastic deformation greater than about 25  $\mu\text{m}$  under a force equivalent to a vertical load of about 200 grams. A pressure or force *F* is applied to back surface **228** of semiconductor die **224** to press tip **296** onto conductive trace **298**. The force *F* can be applied with an elevated temperature. Due to the compliant nature of conductive trace **298**, the conductive trace deforms around tip **296**. In particular, the application of pressure causes conductive trace **298** to undergo a plastic deformation and cover the top surface and side surface of tip **296**.

The conductive traces described in FIGS. **11a-11g**, **12a-12d**, and **13a-13d** can also be compliant material as described in FIGS. **14a-14c**.

FIGS. **15a-15b** show a BOL embodiment of semiconductor die **224** with bump material **304** formed over contact pads **232**, similar to FIG. **10c**. Bump material **304** is generally compliant and undergoes plastic deformation greater than about 25  $\mu\text{m}$  under a force equivalent to a vertical load of about 200 grams. Bump material **304** is wider than conductive trace **306** on substrate **308**. A conductive via **310** is formed through conductive trace **306** with an opening **312** and conductive sidewalls **314**, as shown in FIG. **15a**. Conductive traces **306** is applicable to the no SRO interconnect structure, as described in FIGS. **6-9**.

Semiconductor die **224** is positioned so that bump material **304** is aligned with an interconnect site on conductive trace **306**, see FIGS. **19a-19g**. Alternatively, bump material **304** can be aligned with a conductive pad or other interconnect site formed on substrate **308**. A pressure or force *F* is applied to back surface **228** of semiconductor die **224** to press bump material **304** onto conductive trace **306** and into opening **312** of conductive via **310**. The force *F* can be applied with an elevated temperature. Due to the compliant nature of bump material **304**, the bump material deforms or extrudes around the top surface and side surface of conductive trace **306** and into opening **312** of conductive via **310**, as shown in FIG. **15b**. In particular, the application of pressure causes bump material **304** to undergo a plastic deformation and cover the top surface and side surface of conductive trace **306** and into opening **312** of conductive via **310**. Bump material **304** is thus electrically connected to conductive trace **306** and conductive sidewalls **314** for z-direction vertical interconnect through substrate **308**. The plastic flow of bump material **304** creates a mechanical interlock between the bump material and the top surface and side surface of conductive trace **306** and opening **312** of conductive via **310**. The mechanical interlock between the bump material and the top surface and side surface of conductive trace **306** and opening **312** of conductive via **310** provides a robust connection with greater contact area between the respective surfaces, without significantly increasing the bonding force. The mechanical interlock

between the bump material and the top surface and side surface of conductive trace **306** and opening **312** of conductive via **310** also reduces lateral die shifting during subsequent manufacturing processes, such as encapsulation. Since conductive via **310** is formed within the interconnect site with bump material **304**, the total substrate interconnect area is reduced.

In the BOL embodiments of FIGS. **11a-11g**, **12a-12d**, **13a-13d**, **14a-14c**, and **15a-15b**, by making the conductive trace narrower than the interconnect structure, the conductive trace pitch can be reduced to increase routing density and I/O count. The narrower conductive trace reduces the force *F* needed to deform the interconnect structure around the conductive trace. For example, the requisite force *F* may be 30-50% of the force needed to deform a bump against a conductive trace or pad that is wider than the bump. The lower compressive force *F* is useful for fine pitch interconnect and small die to maintain coplanarity within a specified tolerance and achieve uniform z-direction deformation and high reliability interconnect union. In addition, deforming the interconnect structure around the conductive trace mechanically locks the bump to the trace to prevent die shifting or die floating during reflow.

FIGS. **16a-16c** show a mold underfill (MUF) process to deposit encapsulant around the bumps between the semiconductor die and substrate. FIG. **16a** shows semiconductor die **224** mounted to substrate **254** using bump material **234** from FIG. **11b** and placed between upper mold support **316** and lower mold support **318** of chase mold **320**. The other semiconductor die and substrate combinations from FIGS. **11a-11g**, **12a-12d**, **13a-13d**, **14a-14c**, and **15a-15b** can be placed between upper mold support **316** and lower mold support **318** of chase mold **320**. The upper mold support **316** includes compressible releasing film **322**.

In FIG. **16b**, upper mold support **316** and lower mold support **318** are brought together to enclose semiconductor die **224** and substrate **254** with an open space over the substrate and between the semiconductor die and substrate. Compressible releasing film **322** conforms to back surface **228** and side surface of semiconductor die **224** to block formation of encapsulant on these surfaces. An encapsulant **324** in a liquid state is injected into one side of chase mold **320** with nozzle **326** while an optional vacuum assist **328** draws pressure from the opposite side to uniformly fill the open space over substrate **254** and the open space between semiconductor die **224** and substrate **254** with the encapsulant. Encapsulant **324** can be polymer composite material, such as epoxy resin with filler, epoxy acrylate with filler, or polymer with proper filler. Encapsulant **324** is non-conductive and environmentally protects the semiconductor device from external elements and contaminants. Compressible material **322** prevents encapsulant **324** from flowing over back surface **228** and around the side surface of semiconductor die **224**. Encapsulant **324** is cured. The back surface **228** and side surface of semiconductor die **224** remain exposed from encapsulant **324**.

FIG. **16c** shows an embodiment of MUF and mold overfill (MOF), i.e., without compressible material **322**. Semiconductor die **224** and substrate **254** are placed between upper mold support **316** and lower mold support **318** of chase mold **320**. The upper mold support **316** and lower mold support **318** are brought together to enclose semiconductor die **224** and substrate **254** with an open space over the substrate, around the semiconductor die, and between the semiconductor die and substrate. Encapsulant **324** in a liquid state is injected into one side of chase mold **320** with nozzle **326** while an optional vacuum assist **328** draws pressure from the opposite side to uniformly fill the open space around semiconductor die **224**

and over substrate **254** and the open space between semiconductor die **224** and substrate **254** with the encapsulant. Encapsulant **324** is cured.

FIG. **17** shows another embodiment of depositing encapsulant around semiconductor die **224** and in the gap between semiconductor die **224** and substrate **254**. Semiconductor die **224** and substrate **254** are enclosed by dam **330**. Encapsulant **332** is dispensed from nozzles **334** in a liquid state into dam **330** to fill the open space over substrate **254** and the open space between semiconductor die **224** and substrate **254**. The volume of encapsulant **332** dispensed from nozzles **334** is controlled to fill dam **330** without covering back surface **228** or the side surface of semiconductor die **224**. Encapsulant **332** is cured.

FIG. **18** shows semiconductor die **224** and substrate **254** after the MUF process from FIGS. **16a**, **16c**, and **17**. Encapsulant **324** is uniformly distributed over substrate **254** and around bump material **234** between semiconductor die **224** and substrate **254**.

FIGS. **19a-19g** show top views of various conductive trace layouts on substrate or PCB **340**. In FIG. **19a**, conductive trace **342** is a straight conductor with integrated bump pad or interconnect site **344** formed on substrate **340**, similar to FIG. **6a**. The sides of substrate bump pad **344** can be co-linear with conductive trace **342**. In the prior art, a solder registration opening (SRO) is typically formed over the interconnect site to contain the bump material during reflow. The SRO increases interconnect pitch and reduces I/O count. In contrast, masking layer **346** can be formed over a portion of substrate **340**; however, the masking layer is not formed around substrate bump pad **344** of conductive trace **342**. That is, the portion of conductive trace **342** designed to mate with the bump material is devoid of any SRO of masking layer **346** that would have been used for bump containment during reflow.

Semiconductor die **224** is placed over substrate **340** and the bump material is aligned with substrate bump pads **344**. The bump material is electrically and metallurgically connected to substrate bump pads **344** by bringing the bump material in physical contact with the bump pad and then reflowing the bump material under a reflow temperature.

In another embodiment, an electrically conductive bump material is deposited over substrate bump pad **344** using an evaporation, electrolytic plating, electroless plating, ball drop, or screen printing process. The bump material can be Al, Sn, Ni, Au, Ag, Pb, Bi, Cu, solder, and combinations thereof, with an optional flux solution. For example, the bump material can be eutectic Sn/Pb, high-lead solder, or lead-free solder. The bump material is bonded to substrate bump pad **344** using a suitable attachment or bonding process. In one embodiment, the bump material is reflowed by heating the material above its melting point to form bump or interconnect **348**, as shown in FIG. **19b**. In some applications, bump **348** is reflowed a second time to improve electrical contact to substrate bump pad **344**. The bump material around the narrow substrate bump pad **344** maintains die placement during reflow.

In high routing density applications, it is desirable to minimize escape pitch of conductive traces **342**. The escape pitch between conductive traces **342** can be reduced by eliminating the masking layer for the purpose of reflow containment, i.e., by reflowing the bump material without a masking layer. Since no SRO is formed around die bump pad **232** or substrate bump pad **344**, conductive traces **342** can be formed with a finer pitch, i.e., conductive trace **342** can be disposed closer together or to nearby structures. With no SRO around substrate bump pad **344**, the pitch between conductive traces **342**

is given as  $P=D+PLT+W/2$ , wherein D is the base diameter of bump 348, PLT is die placement tolerance, and W is the width of conductive trace 342. In one embodiment, given a bump base diameter of 100  $\mu\text{m}$ , PLT of 10  $\mu\text{m}$ , and trace line width of 30  $\mu\text{m}$ , the minimum escape pitch of conductive trace 342 is 125  $\mu\text{m}$ . The mask-less bump formation eliminates the need to account for the ligament spacing of masking material between adjacent openings, solder mask registration tolerance (SRT), and minimum resolvable SRO, as found in the prior art.

When the bump material is reflowed without a masking layer to metallurgically and electrically connect die bump pad 232 to substrate bump pad 344, the wetting and surface tension causes the bump material to maintain self-confinement and be retained within the space between die bump pad 232 and substrate bump pad 344 and portion of substrate 340 immediately adjacent to conductive trace 342 substantially within the footprint of the bump pads.

To achieve the desired self-confinement property, the bump material can be immersed in a flux solution prior to placement on die bump pad 232 or substrate bump pad 344 to selectively render the region contacted by the bump material more wettable than the surrounding area of conductive traces 342. The molten bump material remains confined substantially within the area defined by the bump pads due to the wettable properties of the flux solution. The bump material does not run-out to the less wettable areas. A thin oxide layer or other insulating layer can be formed over areas where bump material is not intended to make the area less wettable. Hence, masking layer 340 is not needed around die bump pad 232 or substrate bump pad 344.

FIG. 19c shows another embodiment of parallel conductive traces 352 as a straight conductor with integrated rectangular bump pad or interconnect site 354 formed on substrate 350, similar to FIG. 7b. In this case, substrate bump pad 354 is wider than conductive trace 352, but less than the width of the mating bump. The sides of substrate bump pad 354 can be parallel to conductive trace 352. Masking layer 356 can be formed over a portion of substrate 350; however, the masking layer is not formed around substrate bump pad 354 of conductive trace 352. That is, the portion of conductive trace 352 designed to mate with the bump material is devoid of any SRO of masking layer 356 that would have been used for bump containment during reflow.

FIG. 19d shows another embodiment of conductive traces 360 and 362 arranged in an array of multiple rows with offset integrated bump pad or interconnect site 364 formed on substrate 366 for maximum interconnect escape routing density and capacity. Alternate conductive traces 360 and 362 include an elbow for routing to bump pads 364. The sides of each substrate bump pad 364 is co-linear with conductive traces 360 and 362. Masking layer 368 can be formed over a portion of substrate 366; however, masking layer 368 is not formed around substrate bump pad 364 of conductive traces 360 and 362. That is, the portion of conductive trace 360 and 362 designed to mate with the bump material is devoid of any SRO of masking layer 368 that would have been used for bump containment during reflow.

FIG. 19e shows another embodiment of conductive traces 370 and 372 arranged in an array of multiple rows with offset integrated bump pad or interconnect site 374 formed on substrate 376 for maximum interconnect escape routing density and capacity. Alternate conductive traces 370 and 372 include an elbow for routing to bump pads 374. In this case, substrate bump pad 374 is rounded and wider than conductive traces 370 and 372, but less than the width of the mating interconnect bump material. Masking layer 378 can be formed over a

portion of substrate 376; however, masking layer 378 is not formed around substrate bump pad 374 of conductive traces 370 and 372. That is, the portion of conductive trace 370 and 372 designed to mate with the bump material is devoid of any SRO of masking layer 378 that would have been used for bump containment during reflow.

FIG. 19f shows another embodiment of conductive traces 380 and 382 arranged in an array of multiple rows with offset integrated bump pad or interconnect site 384 formed on substrate 386 for maximum interconnect escape routing density and capacity. Alternate conductive traces 380 and 382 include an elbow for routing to bump pads 384. In this case, substrate bump pad 384 is rectangular and wider than conductive traces 380 and 382, but less than the width of the mating interconnect bump material. Masking layer 388 can be formed over a portion of substrate 386; however, masking layer 388 is not formed around substrate bump pad 384 of conductive traces 380 and 382. That is, the portion of conductive trace 380 and 382 designed to mate with the bump material is devoid of any SRO of masking layer 388 that would have been used for bump containment during reflow.

As one example of the interconnect process, semiconductor die 224 is placed over substrate 366 and bump material 234 is aligned with substrate bump pads 364 from FIG. 19d. Bump material 234 is electrically and metallurgically connected to substrate bump pad 364 by pressing the bump material or by bringing the bump material in physical contact with the bump pad and then reflowing the bump material under a reflow temperature, as described for FIGS. 11a-11g, 12a-12d, 13a-13d, 14a-14c, and 15a-15b.

In another embodiment, an electrically conductive bump material is deposited over substrate bump pad 364 using an evaporation, electrolytic plating, electroless plating, ball drop, or screen printing process. The bump material can be Al, Sn, Ni, Au, Ag, Pb, Bi, Cu, solder, and combinations thereof, with an optional flux solution. For example, the bump material can be eutectic Sn/Pb, high-lead solder, or lead-free solder. The bump material is bonded to substrate bump pad 364 using a suitable attachment or bonding process. In one embodiment, the bump material is reflowed by heating the material above its melting point to form bump or interconnect 390, as shown in FIG. 19g. In some applications, bump 390 is reflowed a second time to improve electrical contact to substrate bump pad 364. The bump material around the narrow substrate bump pad 364 maintains die placement during reflow. Bump material 234 or bumps 390 can also be formed on substrate bump pad configurations of FIGS. 19a-19g.

In high routing density applications, it is desirable to minimize escape pitch of conductive traces 360 and 362 or other conductive trace configurations of FIGS. 19a-19g. The escape pitch between conductive traces 360 and 362 can be reduced by eliminating the masking layer for the purpose of reflow containment, i.e., by reflowing the bump material without a masking layer. Since no SRO is formed around die bump pad 232 or substrate bump pad 364, conductive traces 360 and 362 can be formed with a finer pitch, i.e., conductive traces 360 and 362 can be disposed closer together or to nearby structures. With no SRO around substrate bump pad 364, the pitch between conductive traces 360 and 362 is given as  $D/2+PLT+W/2$ , wherein D is the base diameter of bump 390, PLT is die placement tolerance, and W is the width of conductive traces 360 and 362. In one embodiment, given a bump base diameter of 100  $\mu\text{m}$ , PLT of 10  $\mu\text{m}$ , and trace line width of 30  $\mu\text{m}$ , the minimum escape pitch of conductive traces 360 and 362 is 125  $\mu\text{m}$ . The mask-less bump formation eliminates the need to account for the ligament spacing of

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masking material between adjacent openings, SRT, and minimum resolvable SRO, as found in the prior art.

When the bump material is reflowed without a masking layer to metallurgically and electrically connect die bump pad 232 to substrate bump pad 364, the wetting and surface tension causes the bump material to maintain self-confinement and be retained within the space between die bump pad 232 and substrate bump pad 364 and portion of substrate 366 immediately adjacent to conductive traces 360 and 362 substantially within the footprint of the bump pads.

To achieve the desired self-confinement property, the bump material can be immersed in a flux solution prior to placement on die bump pad 232 or substrate bump pad 364 to selectively render the region contacted by the bump material more wettable than the surrounding area of conductive traces 360 and 362. The molten bump material remains confined substantially within the area defined by the bump pads due to the wettable properties of the flux solution. The bump material does not run-out to the less wettable areas. A thin oxide layer or other insulating layer can be formed over areas where bump material is not intended to make the area less wettable. Hence, masking layer 368 is not needed around die bump pad 232 or substrate bump pad 364.

In FIG. 20a, masking layer 392 is deposited over a portion of conductive traces 394 and 396. However, masking layer 392 is not formed over integrated bump pads 398. Consequently, there is no SRO for each bump pad 398 on substrate 400. A non-wettable masking patch 402 is formed on substrate 400 interstitially within the array of integrated bump pads 398, i.e., between adjacent bump pads. The masking patch 402 can also be formed on semiconductor die 224 interstitially within the array of die bump pads 398. More generally, the masking patch is formed in close proximity to the integrated bump pads in any arrangement to prevent run-out to less wettable areas.

Semiconductor die 224 is placed over substrate 400 and the bump material is aligned with substrate bump pads 398. The bump material is electrically and metallurgically connected to substrate bump pad 398 by pressing the bump material or by bringing the bump material in physical contact with the bump pad and then reflowing the bump material under a reflow temperature, as described for FIGS. 11a-11g, 12a-12d, 13a-13d, 14a-14c, and 15a-15b.

In another embodiment, an electrically conductive bump material is deposited over die integrated bump pads 398 using an evaporation, electrolytic plating, electroless plating, ball drop, or screen printing process. The bump material can be Al, Sn, Ni, Au, Ag, Pb, Bi, Cu, solder, and combinations thereof, with an optional flux solution. For example, the bump material can be eutectic Sn/Pb, high-lead solder, or lead-free solder. The bump material is bonded to integrated bump pads 398 using a suitable attachment or bonding process. In one embodiment, the bump material is reflowed by heating the material above its melting point to form spherical balls or bumps 404, as shown in FIG. 20b. In some applications, bumps 404 are reflowed a second time to improve electrical contact to integrated bump pads 398. The bumps can also be compression bonded to integrated bump pads 398. Bumps 404 represent one type of interconnect structure that can be formed over integrated bump pads 398. The interconnect structure can also use stud bump, micro bump, or other electrical interconnect.

In high routing density applications, it is desirable to minimize escape pitch. In order to reduce the pitch between conductive traces 394 and 396, the bump material is reflowed without a masking layer around integrated bump pads 398. The escape pitch between conductive traces 394 and 396 can

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be reduced by eliminating the masking layer and associated SROs around the integrated bump pads for the purpose of reflow containment, i.e., by reflowing the bump material without a masking layer. Masking layer 392 can be formed over a portion of conductive traces 394 and 396 and substrate 400 away from integrated bump pads 398; however, masking layer 392 is not formed around integrated bump pads 398. That is, the portion of conductive trace 394 and 396 designed to mate with the bump material is devoid of any SRO of masking layer 392 that would have been used for bump containment during reflow.

In addition, masking patch 402 is formed on substrate 400 interstitially within the array of integrated bump pads 398. Masking patch 402 is non-wettable material. Masking patch 402 can be the same material as masking layer 392 and applied during the same processing step, or a different material during a different processing step. Masking patch 402 can be formed by selective oxidation, plating, or other treatment of the portion of the trace or pad within the array of integrated bump pads 398. Masking patch 402 confines bump material flow to integrated bump pads 398 and prevents leaching of conductive bump material to adjacent structures.

When the bump material is reflowed with masking patch 402 interstitially disposed within the array of integrated bump pads 398, the wetting and surface tension causes the bump material to be confined and retained within the space between die bump pads 232 and integrated bump pads 398 and portion of substrate 400 immediately adjacent to conductive traces 394 and 396 and substantially within the footprint of the integrated bump pads 398.

To achieve the desired confinement property, the bump material can be immersed in a flux solution prior to placement on die bump pads 232 or integrated bump pads 398 to selectively render the region contacted by the bump material more wettable than the surrounding area of conductive traces 394 and 396. The molten bump material remains confined substantially within the area defined by the bump pads due to the wettable properties of the flux solution. The bump material does not run-out to the less wettable areas. A thin oxide layer or other insulating layer can be formed over areas where bump material is not intended to make the area less wettable. Hence, masking layer 392 is not needed around die bump pads 232 or integrated bump pads 398.

Since no SRO is formed around die bump pads 232 or integrated bump pads 398, conductive traces 394 and 396 can be formed with a finer pitch, i.e., the conductive traces can be disposed closer to adjacent structures without making contact and forming electrical shorts. Assuming the same solder registration design rule, the pitch between conductive traces 394 and 396 is given as  $P=(1.1D+W)/2$ , where D is the base diameter of bump 404 and W is the width of conductive traces 394 and 396. In one embodiment, given a bump diameter of 100  $\mu\text{m}$  and trace line width of 20  $\mu\text{m}$ , the minimum escape pitch of conductive traces 394 and 396 is 65  $\mu\text{m}$ . The bump formation eliminates the need to account for the ligament spacing of masking material between adjacent openings and minimum resolvable SRO, as found in the prior art.

FIG. 21 shows package-on-package (PoP) 405 with semiconductor die 406 stacked over semiconductor die 408 using die attach adhesive 410. Semiconductor die 406 and 408 each have an active surface containing analog or digital circuits implemented as active devices, passive devices, conductive layers, and dielectric layers formed within the die and electrically interconnected according to the electrical design and function of the die. For example, the circuit can include one or more transistors, diodes, and other circuit elements formed within the active surface to implement analog circuits or

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digital circuits, such as DSP, ASIC, memory, or other signal processing circuit. Semiconductor die **406** and **408** can also contain IPDs, such as inductors, capacitors, and resistors, for RF signal processing.

Semiconductor die **406** is mounted to conductive traces **412** formed on substrate **414** using bump material **416** formed on contact pads **418**, using any of the embodiments from FIGS. **11a-11g**, **12a-12d**, **13a-13d**, **14a-14c**, and **15a-15b**. Conductive traces **412** is applicable to the no SRO interconnect structure, as described in FIGS. **6-9**. Semiconductor die **408** is electrically connected to contact pads **420** formed on substrate **414** using bond wires **422**. The opposite end of bond wire **422** is bonded to contact pads **424** on semiconductor die **406**.

Masking layer **426** is formed over substrate **414** and opened beyond the footprint of semiconductor die **406**. While masking layer **426** does not confine bump material **416** to conductive traces **412** during reflow, the open mask can operate as a dam to prevent encapsulant **428** from migrating to contact pads **420** or bond wires **422** during MUF. Encapsulant **428** is deposited between semiconductor die **408** and substrate **414**, similar to FIGS. **16a-16c**. Masking layer **426** blocks MUF encapsulant **428** from reaching contact pads **420** and bond wires **422**, which could cause a defect. Masking layer **426** allows a larger semiconductor die to be placed on a given substrate without risk of encapsulant **428** bleeding onto contact pads **420**.

While one or more embodiments of the present invention have been illustrated in detail, the skilled artisan will appreciate that modifications and adaptations to those embodiments may be made without departing from the scope of the present invention as set forth in the following claims.

What is claimed:

1. A method of making a semiconductor device, comprising:

providing a first semiconductor structure including a first interconnect site;  
providing a second semiconductor structure including a second interconnect site;  
depositing a conductive material self-confined between the first interconnect site and second interconnect site by a wettable state of the conductive material; and  
forming an insulating layer around the first interconnect site.

2. The method of claim 1, further including depositing an encapsulant between the first semiconductor structure and second semiconductor structure.

3. The method of claim 1, further including selecting a volume of conductive material deposited between the first interconnect site and second interconnect site to maintain self-confinement of the conductive material.

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4. The method of claim 1, wherein the conductive material covers a top surface and side surface of the first interconnect site or second interconnect site.

5. The method of claim 1, wherein the conductive material includes a fusible portion and non-fusible portion.

6. The method of claim 1, further including immersing the conductive material in a flux solution.

7. A semiconductor device, comprising:  
a first semiconductor structure including a first interconnect site;  
a second semiconductor structure including a second interconnect site;

a conductive material disposed between the interconnect site and conductive trace to form an interconnect structure without a mask bonding the first semiconductor structure and second semiconductor structure; and  
an insulating layer formed around the first interconnect site.

8. The semiconductor device of claim 7, further including an encapsulant deposited between the first semiconductor structure and second semiconductor structure.

9. The semiconductor device of claim 7, wherein the conductive material is self-confined between the first interconnect site and second interconnect site.

10. The semiconductor device of claim 7, wherein the interconnect structure covers a top surface and side surface of the first interconnect site or second interconnect site.

11. The semiconductor device of claim 7, wherein the interconnect structure includes a fusible portion and non-fusible portion.

12. A semiconductor device, comprising:  
a first semiconductor structure including a first interconnect site;  
a second semiconductor structure including a second interconnect site; and  
a conductive material self-confined between the first interconnect site and second interconnect site.

13. The semiconductor device of claim 12, further including an encapsulant deposited between the first semiconductor structure and second semiconductor structure.

14. The semiconductor device of claim 12, wherein the conductive material covers a top surface and side surface of the first interconnect site or second interconnect site.

15. The semiconductor device of claim 12, wherein the conductive material includes a fusible portion and non-fusible portion.

16. The semiconductor device of claim 12, further including an insulating layer formed around the first interconnect site.

17. The semiconductor device of claim 12, further including a flux solution deposited over the conductive material.

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